

Fulvio Tassarotto (INFN – Trieste)
on behalf of the COMPASS RICH Group

The COMPASS RICH-1 upgrade

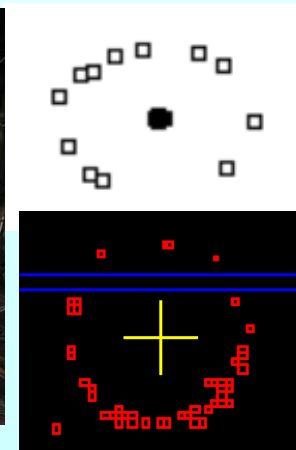
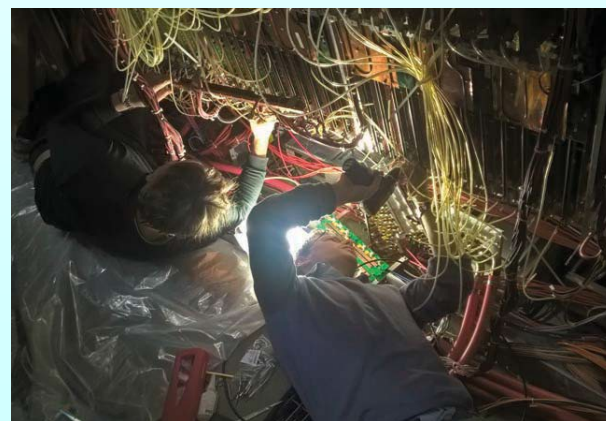
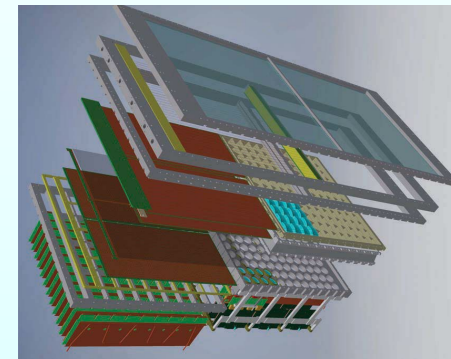
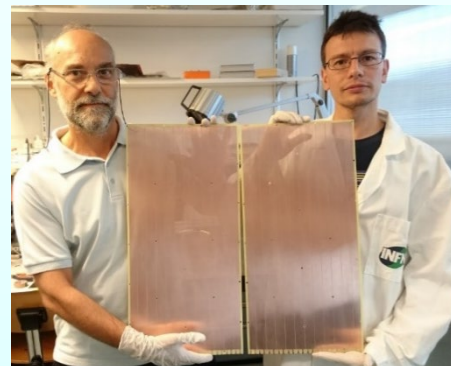
The MPGD-based PD design and construction

HV control, spark rates, noise level

Uniformity and stability

MPGD-based PD characterization

Conclusions

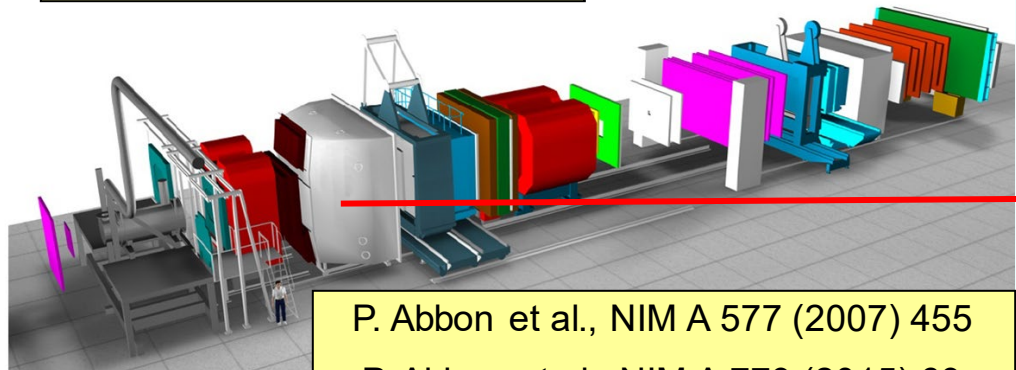


The 2024 International Workshop on Future Tau Charm Facilities



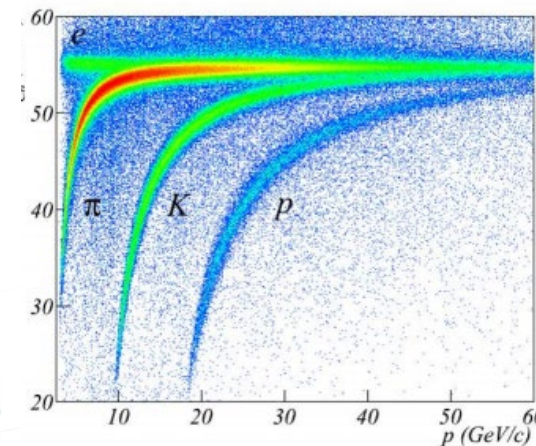
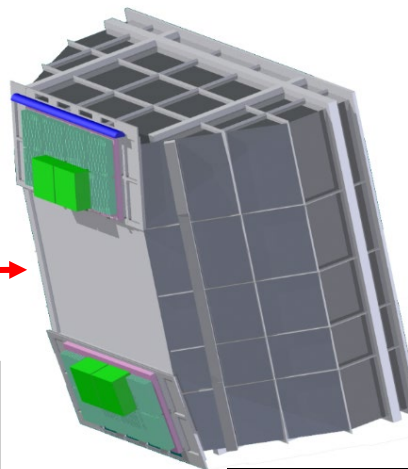
COMPASS RICH-1 upgrade

COMPASS Spectrometer



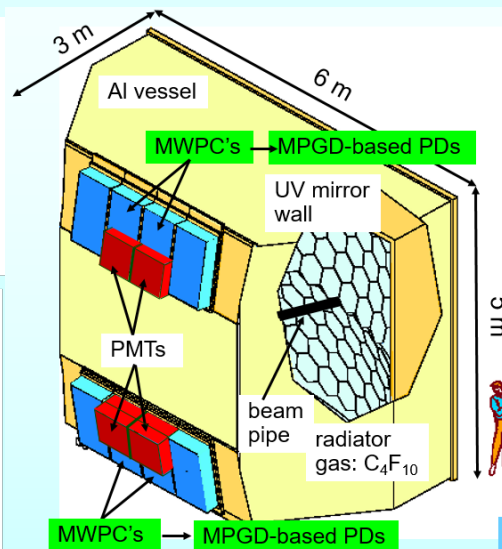
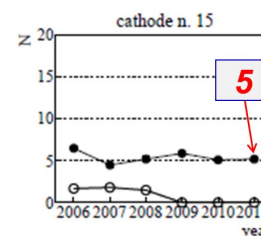
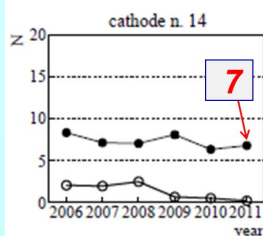
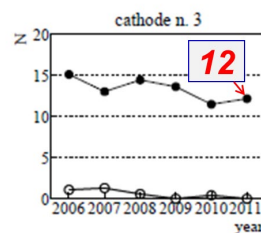
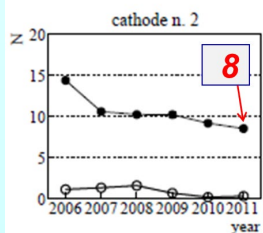
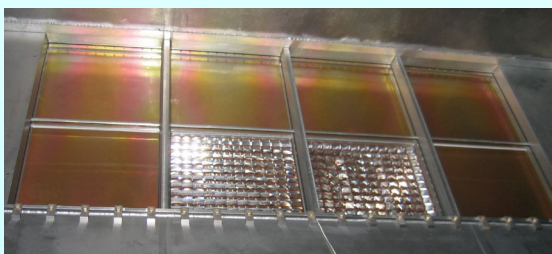
P. Abbon et al., NIM A 577 (2007) 455

P. Abbon et al., NIM A 779 (2015) 69

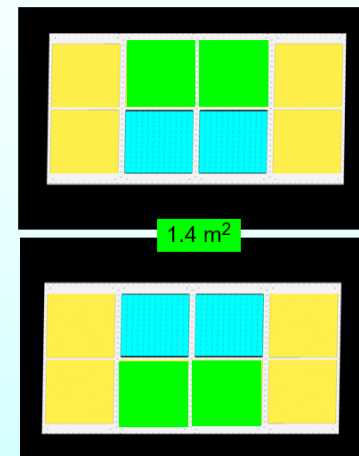


F. Tassarotto et al., JINST 9 (2014) C09011

acceptance: H: 500 mrad V: 400 mrad; beam rates up to $\sim 10^8$ Hz; 2.4% X_0 (beam region), 22% X_0 (acceptance) $80 \text{ m}^3 \text{ C}_4\text{F}_{10}$, 21 m^2 UV mirrors, 1.4 m^2 MAPMTs, 4 m^2 gaseous PDs



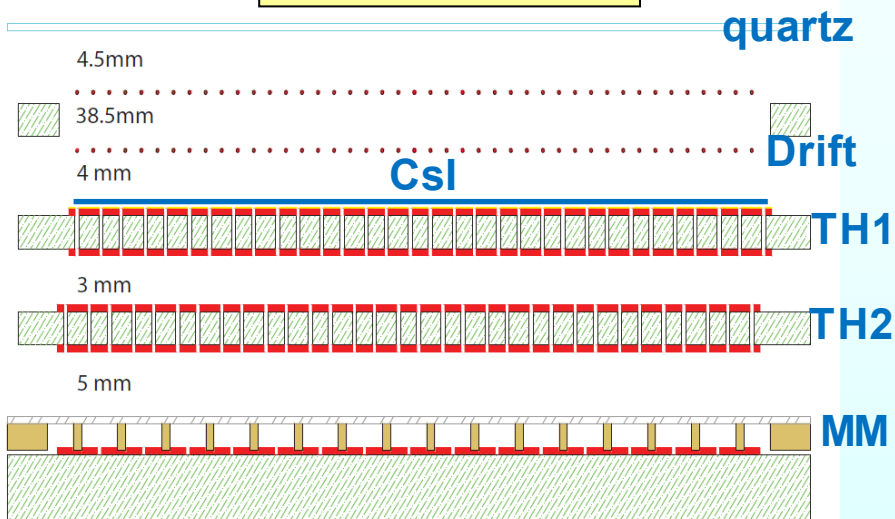
for COMPASS run 2016



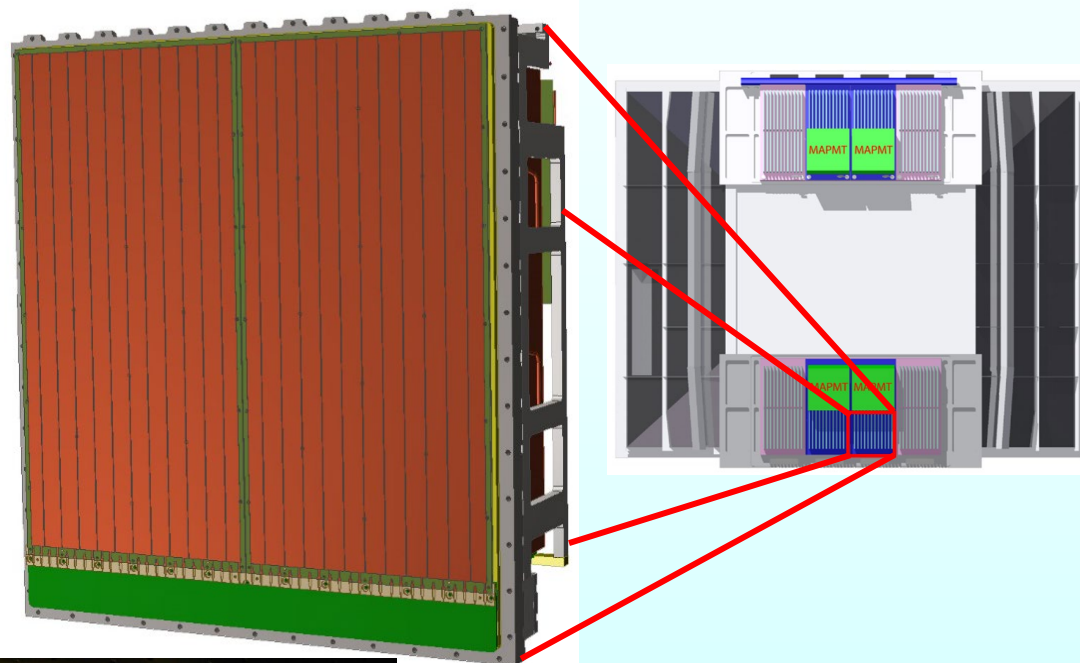
4 new detectors of 600 mm x 600 mm

MWPCs+CsI: successful but with important performance limitations, in particular in the case of the 4 central chambers

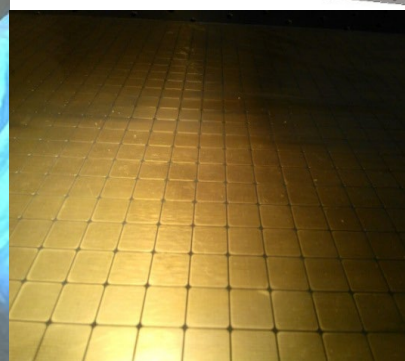
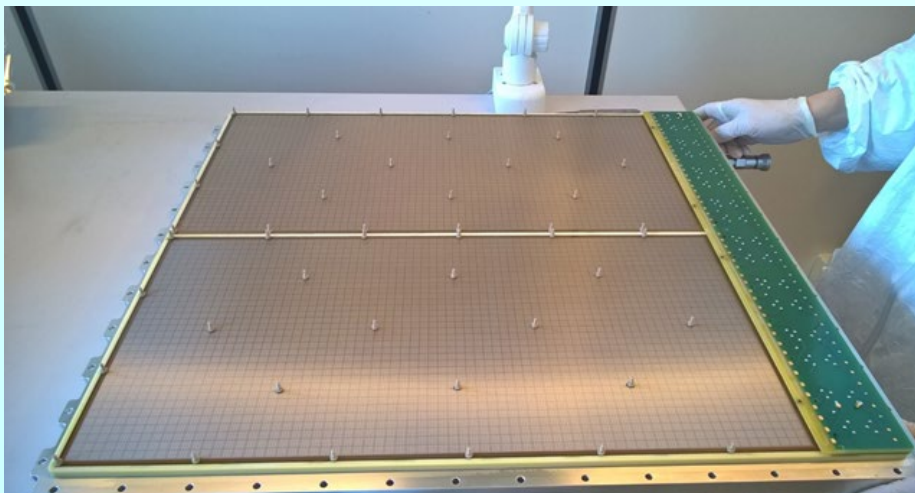
Hybrid PD scheme



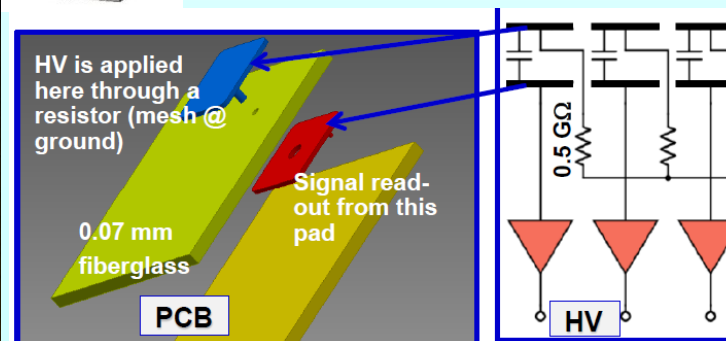
modular structure: one module = 600x300 mm²



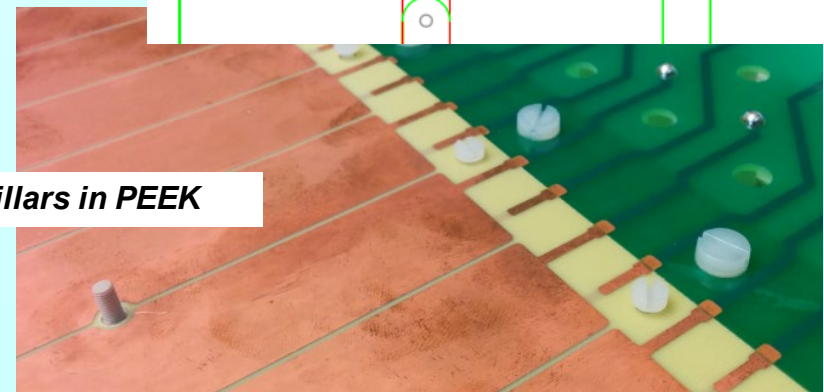
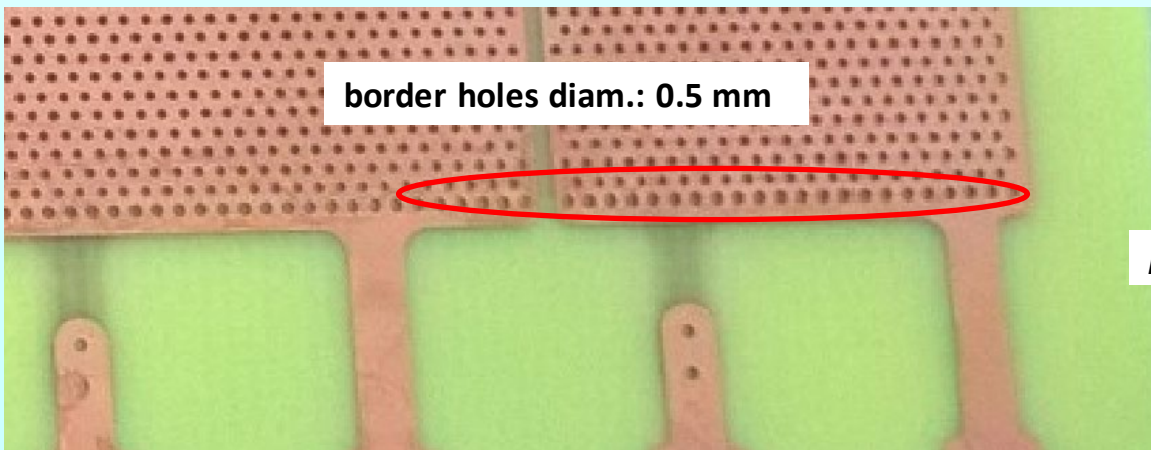
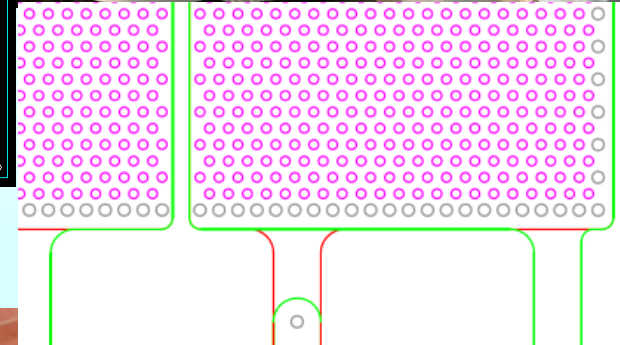
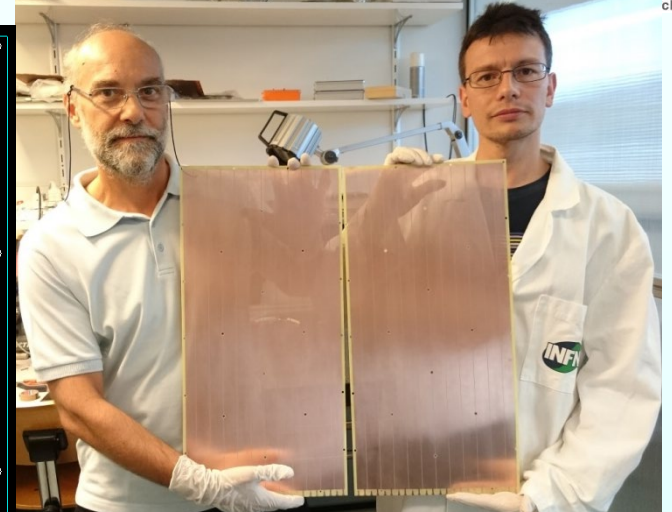
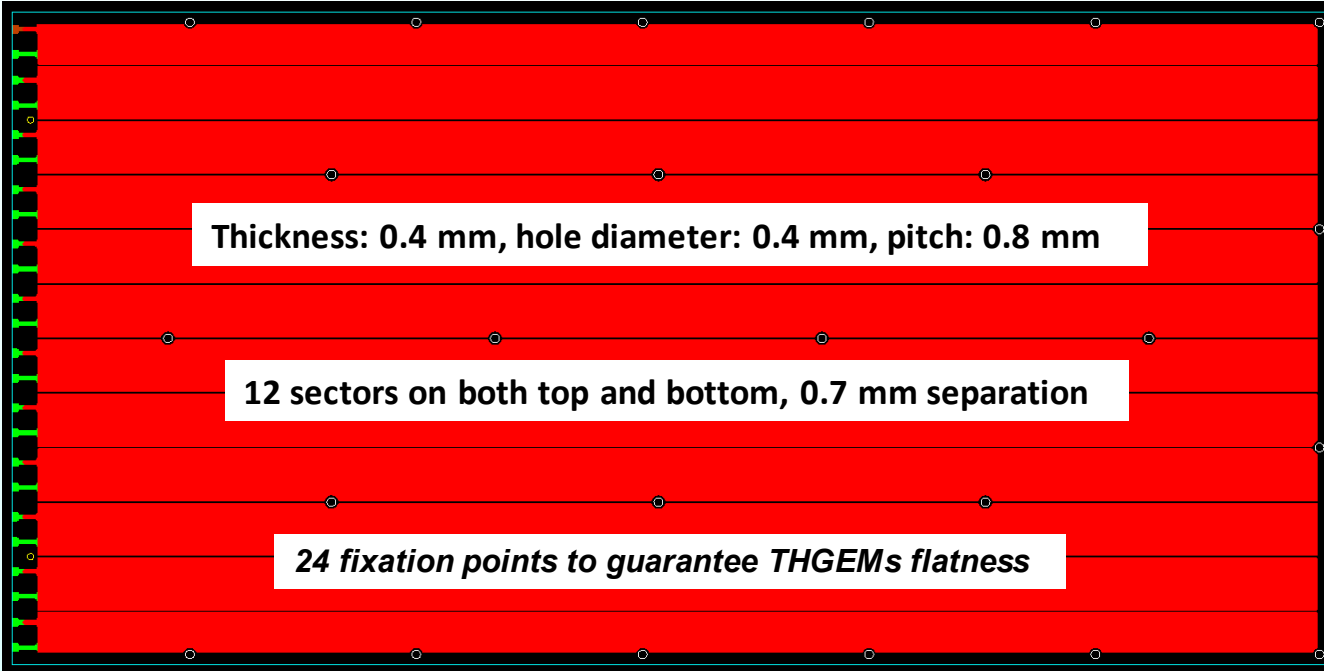
Standard Bulk Micromegas produced at CERN



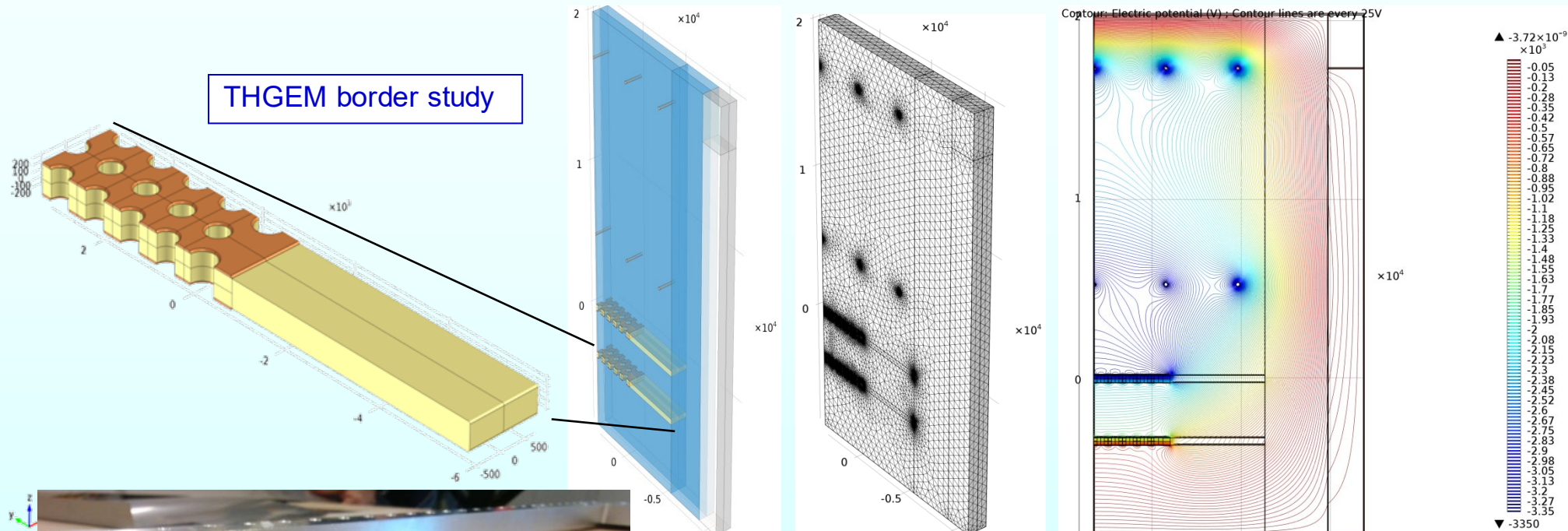
8mm X 8mm pads at positive HV



Capacitive coupling → APV25



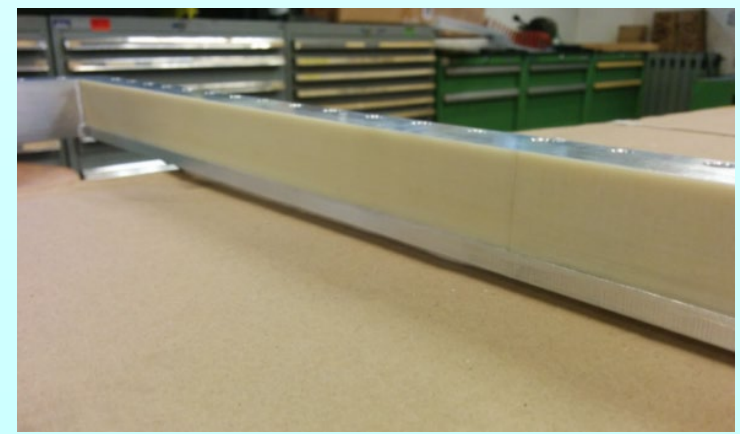
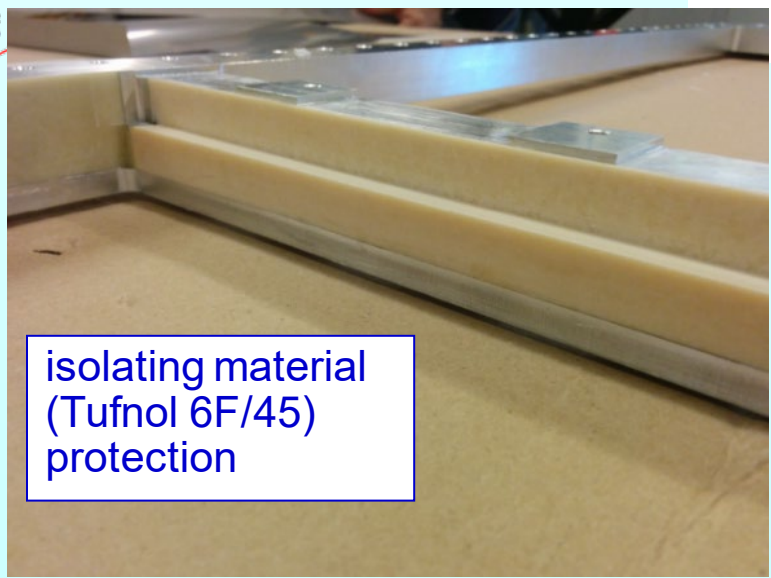
THGEM border study



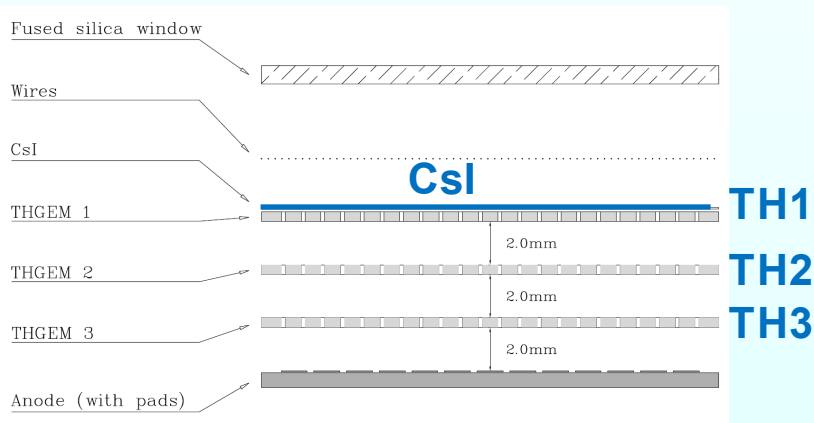
large field values at the chamber edges and on the guard wires

Field shaping electrodes in the isolating material protections of the chamber frames

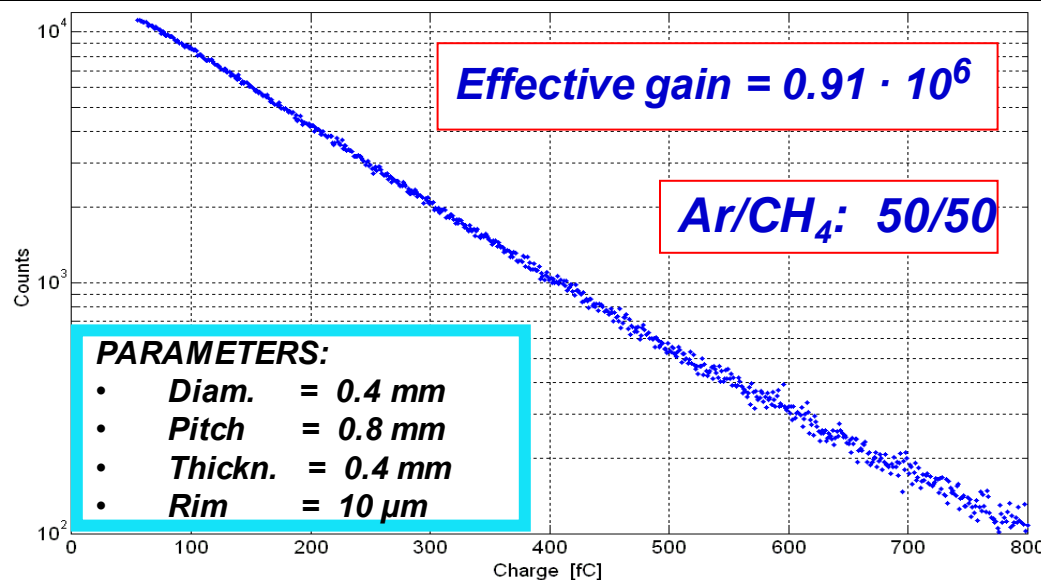
isolating material (Tufnol 6F/45) protection



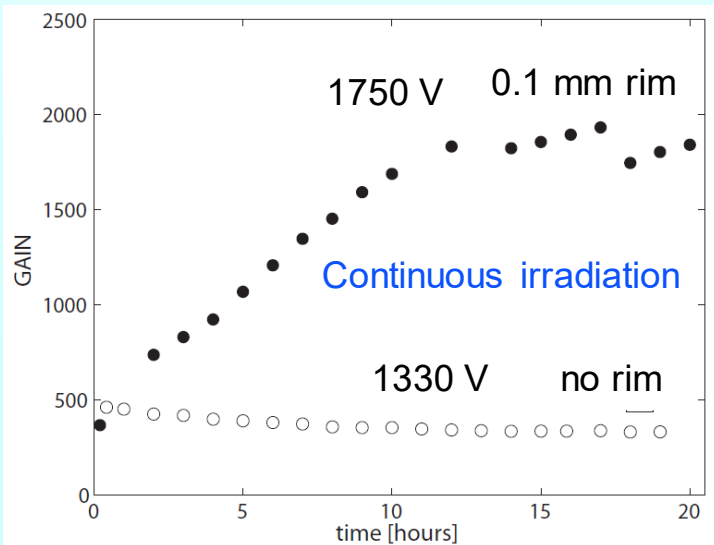
Triple THGEM



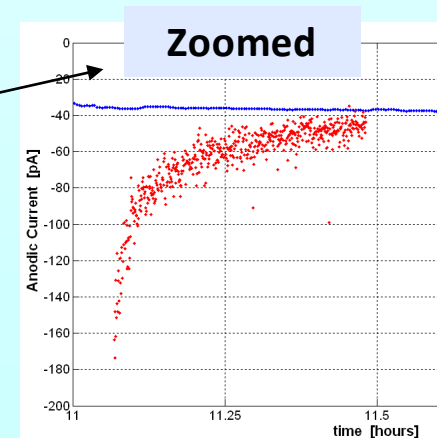
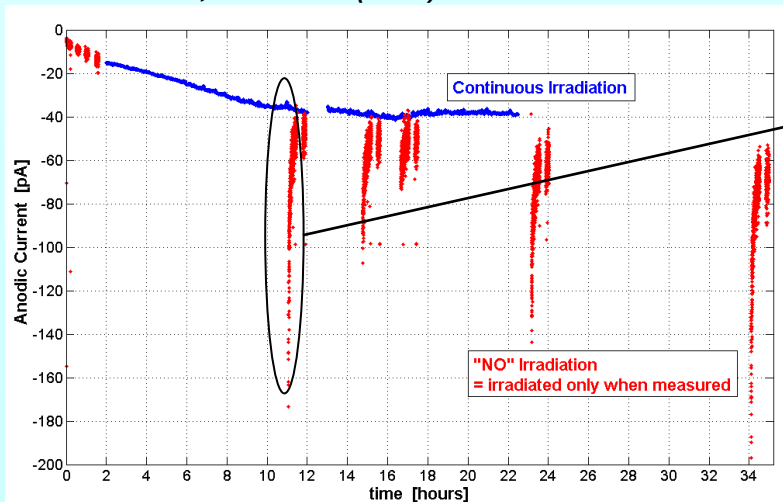
High gain obtained in a 3THGEM with 30x30 mm² active area

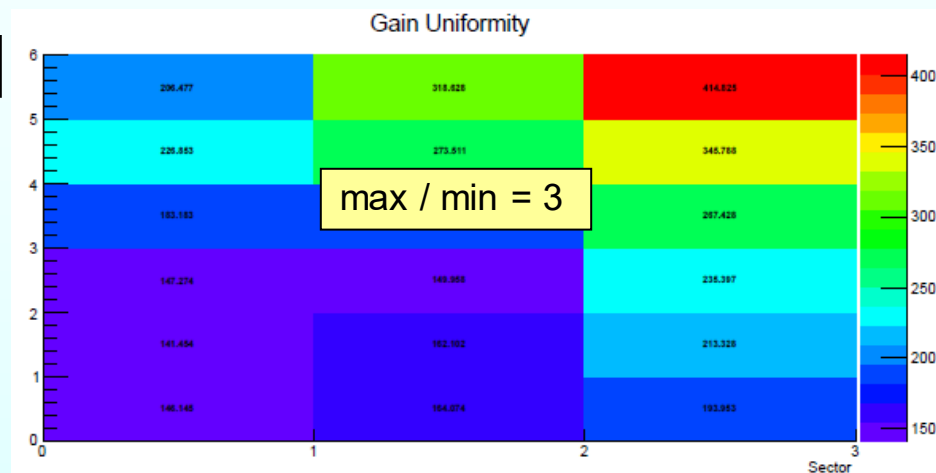
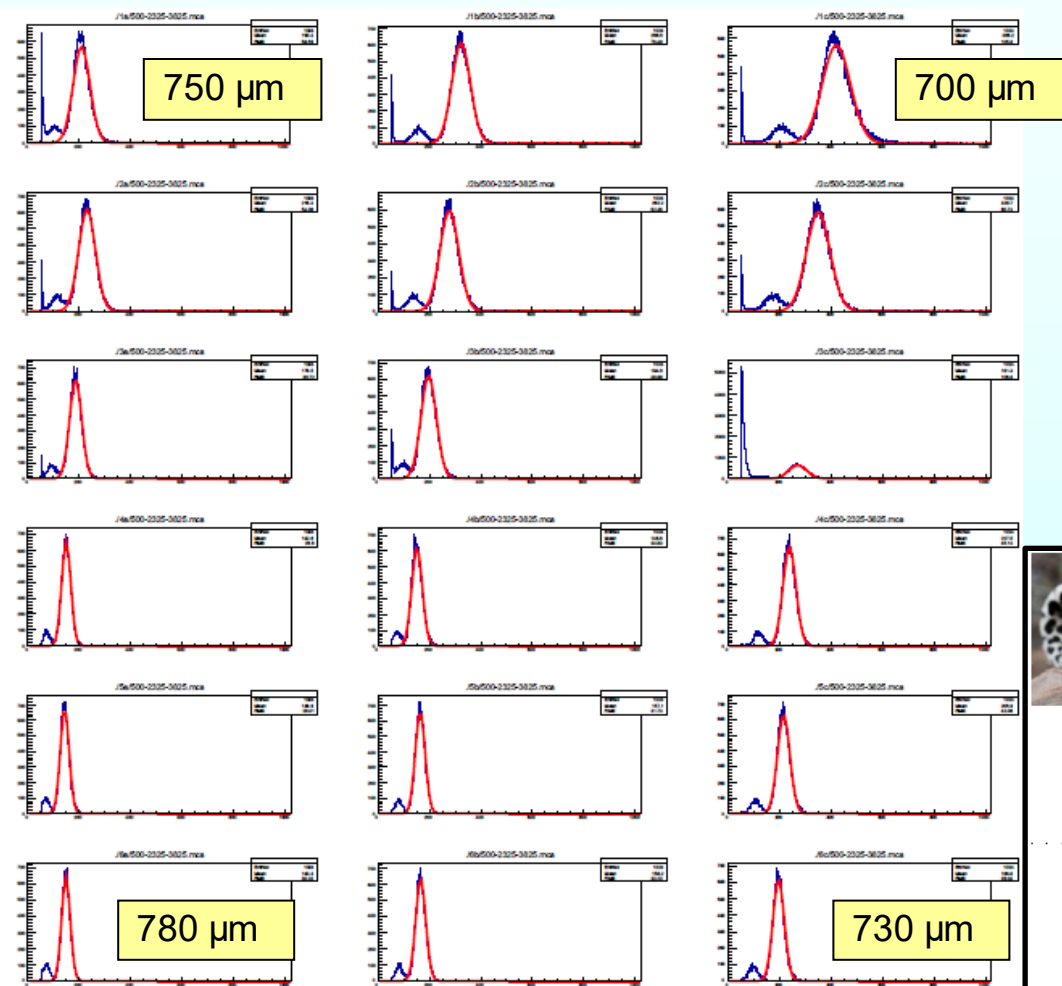


Rim ≠ 0 → difficult to control the gain

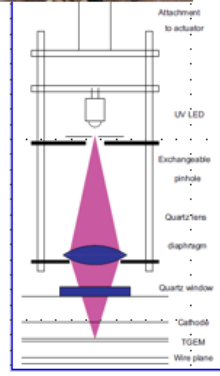
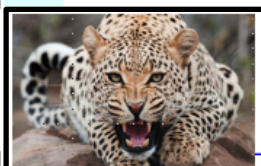


M. Alexeev et al., NIMA 617 (2010) 396

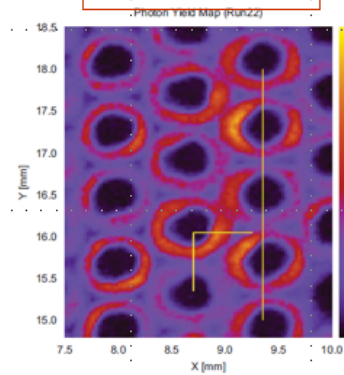




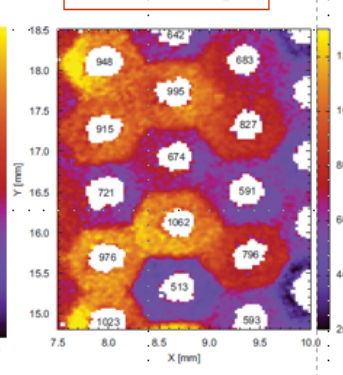
Local non uniformities



Efficiency map



Gain map



G.Hamar and D. Varga, NIMA 694(2012)16

➔ Strict thickness uniformity requirement



THGEM raw material selection

Our thickness uniformity requirements are stricter than those offered by producers → material selection

50 foils of 1245 mm x 1092 mm → cut out borders → 800 mm x 800 mm → thickness measurement



Elite Material Co., Ltd.

Technical Data

<http://www.emctv.com>

Lead-free , Halogen-free Material

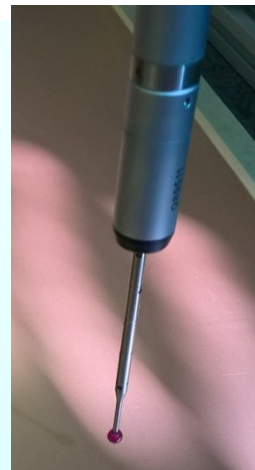
PRODUCT EM 370-5

Thickness 0.407 mm

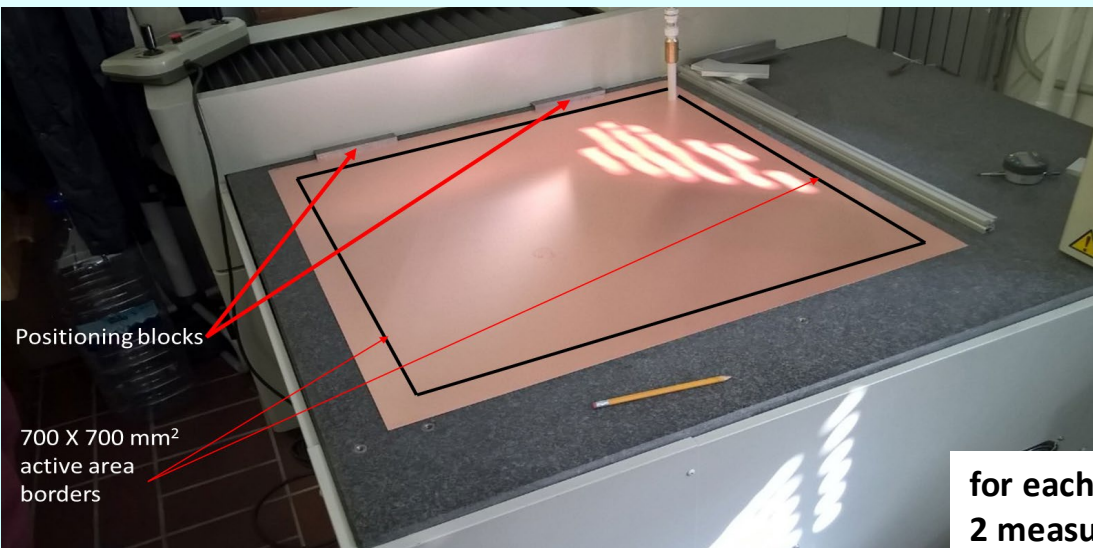
Copper 35μ / 35μ

Sheet Size 1 245 x 1 092 mm

Permittivity (RC 50%)	1 MHz	2.5.5.9	C-24/23/50	-	4.8
	1 GHz			-	4.3
Volume resistivity	2.5.17.1	C-96/35/90	MQ-cm	>10 ¹⁰	
Surface resistivity	2.5.17.1	C-96/35/90	MQ	>10 ⁹	

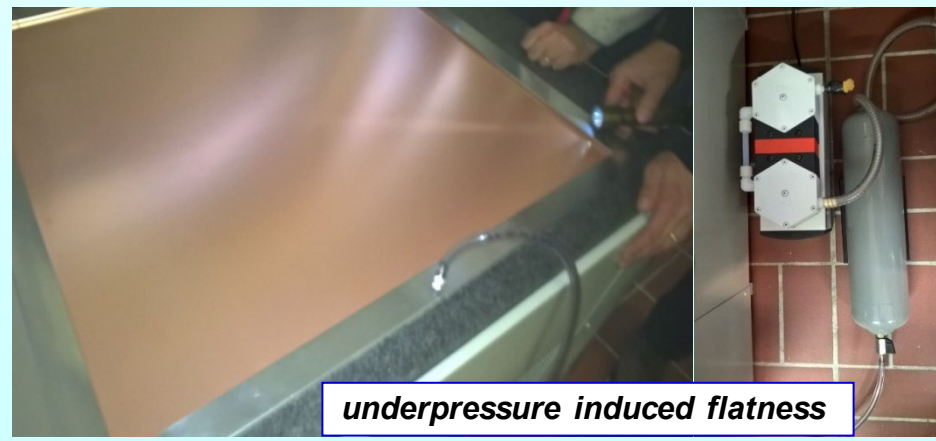


Mitutoyo EURO CA776
coordinate measuring machine with ruby touch probe,
hosted in a thermalized room



Positioning blocks

700 X 700 mm² active area borders

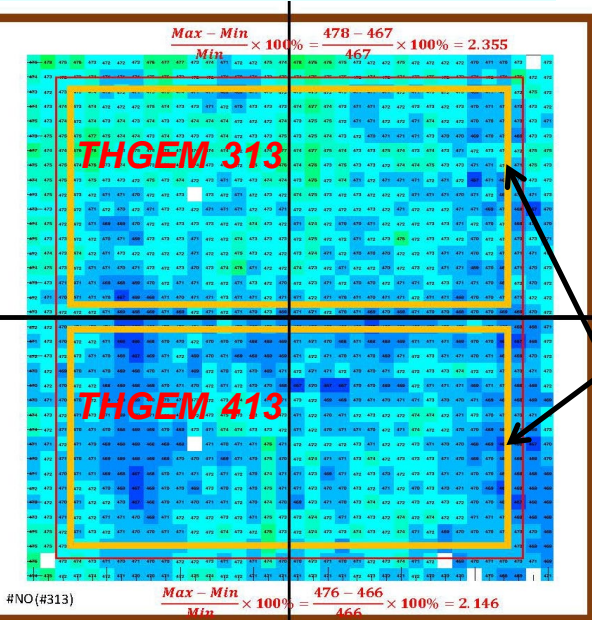
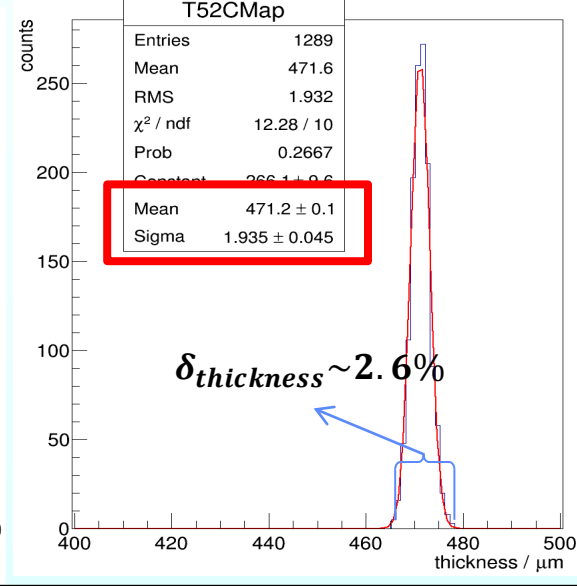
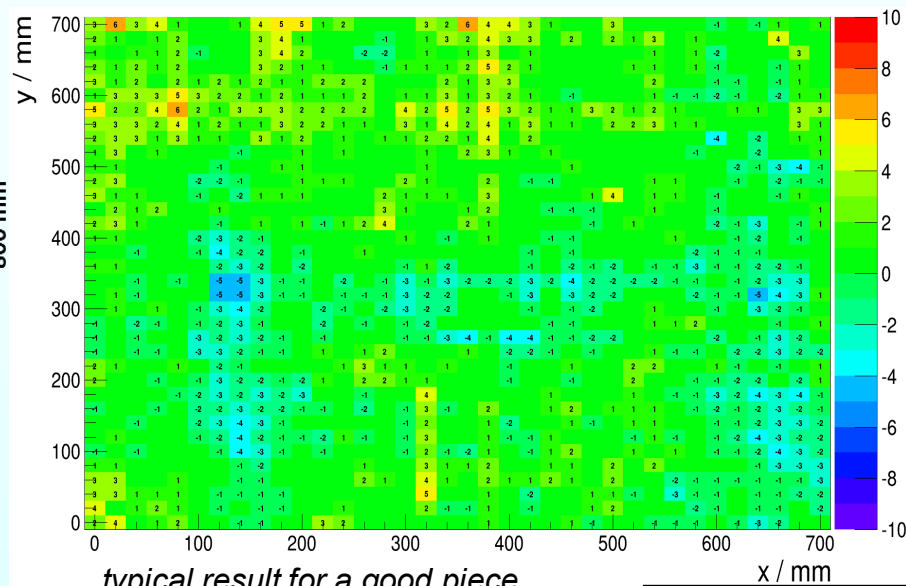
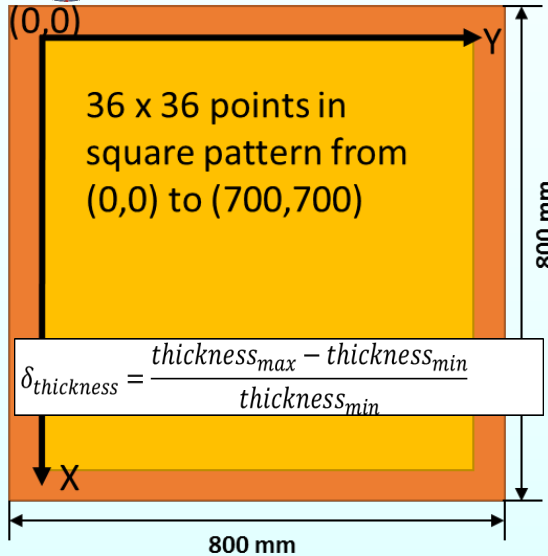


underpressure induced flatness

for each foil 36 x 36 points in square pattern are measured
2 measurements (direct and reversed) to allow consistency checks.



THGEM raw material selection



all foils have been labelled and measured → database of local thickness of all THGEMS

from each foil two THGEMS can be produced:
 50 foils → 100 raw THGEM pcb
 THGEM pcb size = 620 mm x 320 mm,
 active area = 581 mm x 287 mm

60 THGEMS have been produced by ELTOS

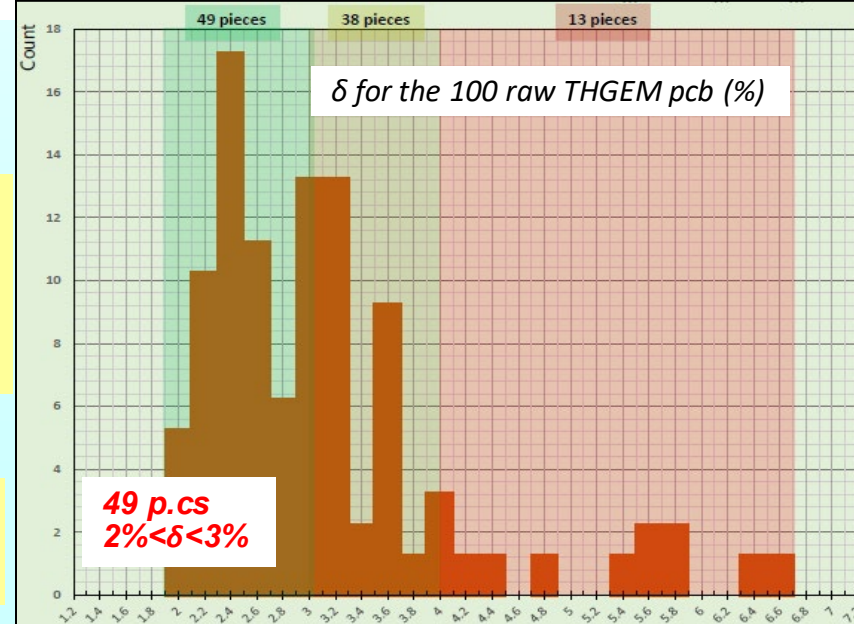
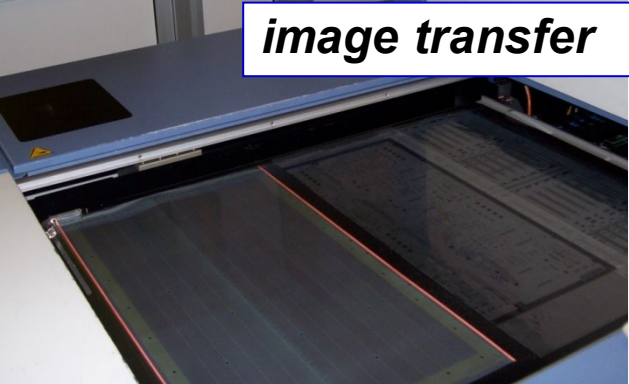


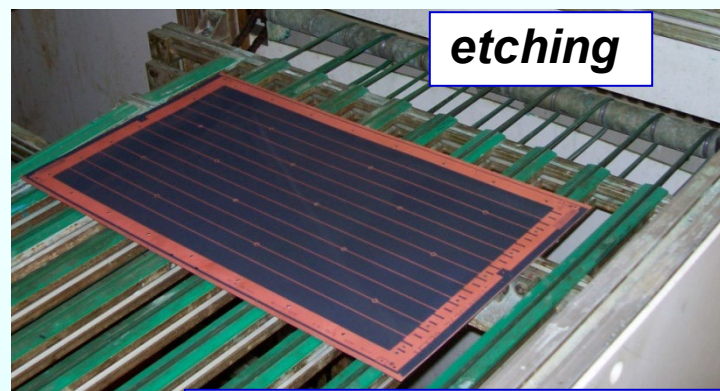
image transfer



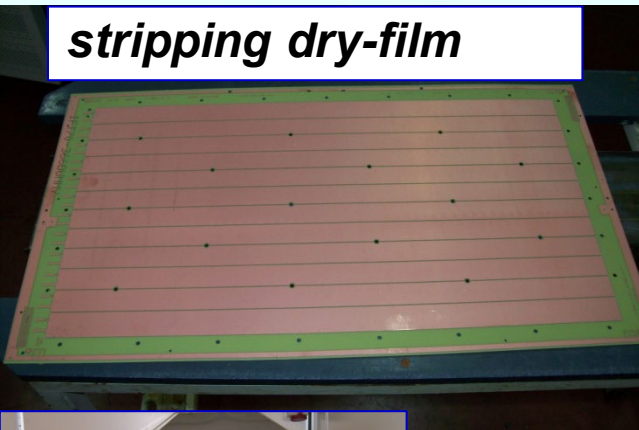
development



etching



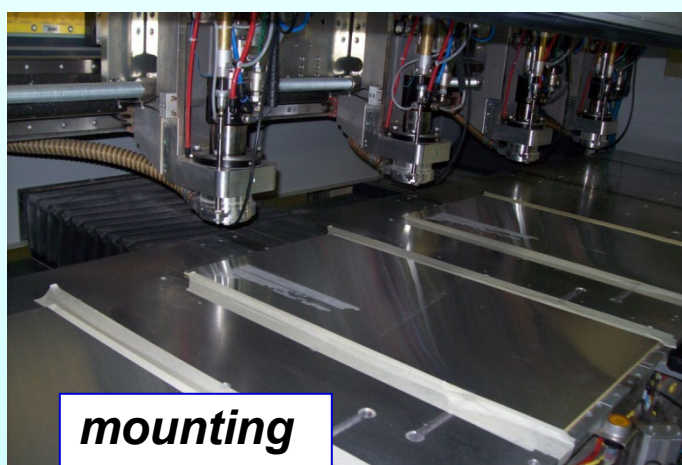
stripping dry-film



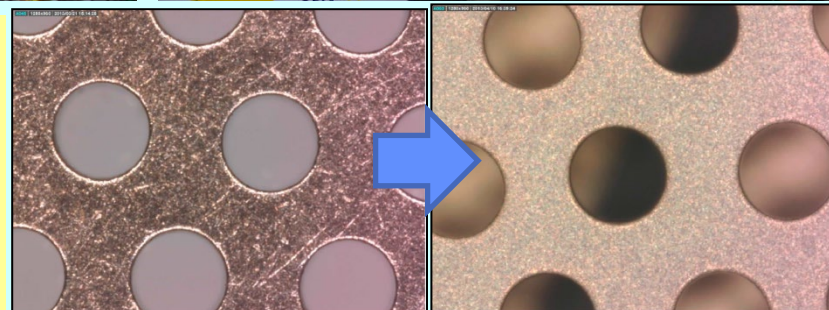
multi-spindle drilling

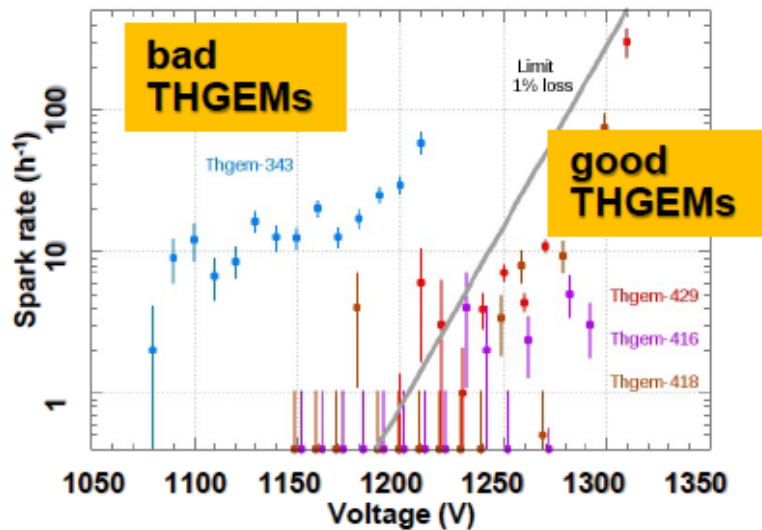
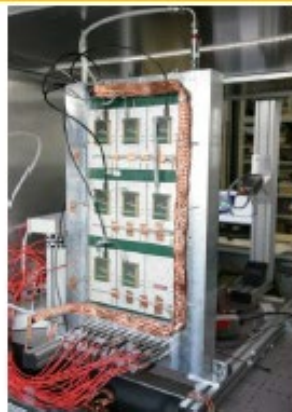
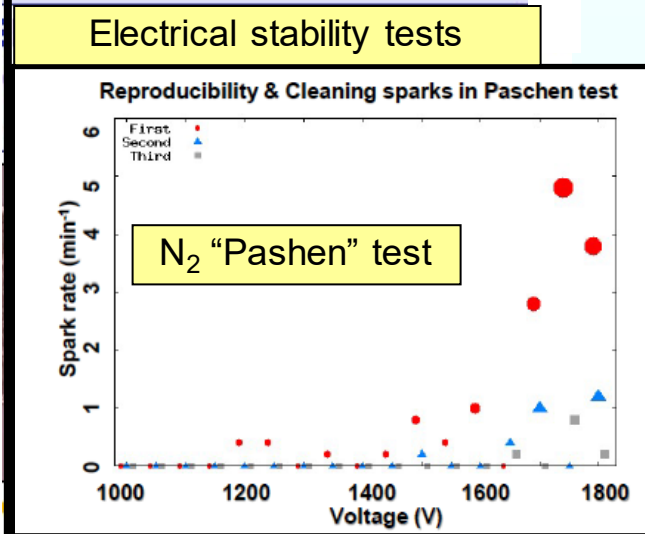
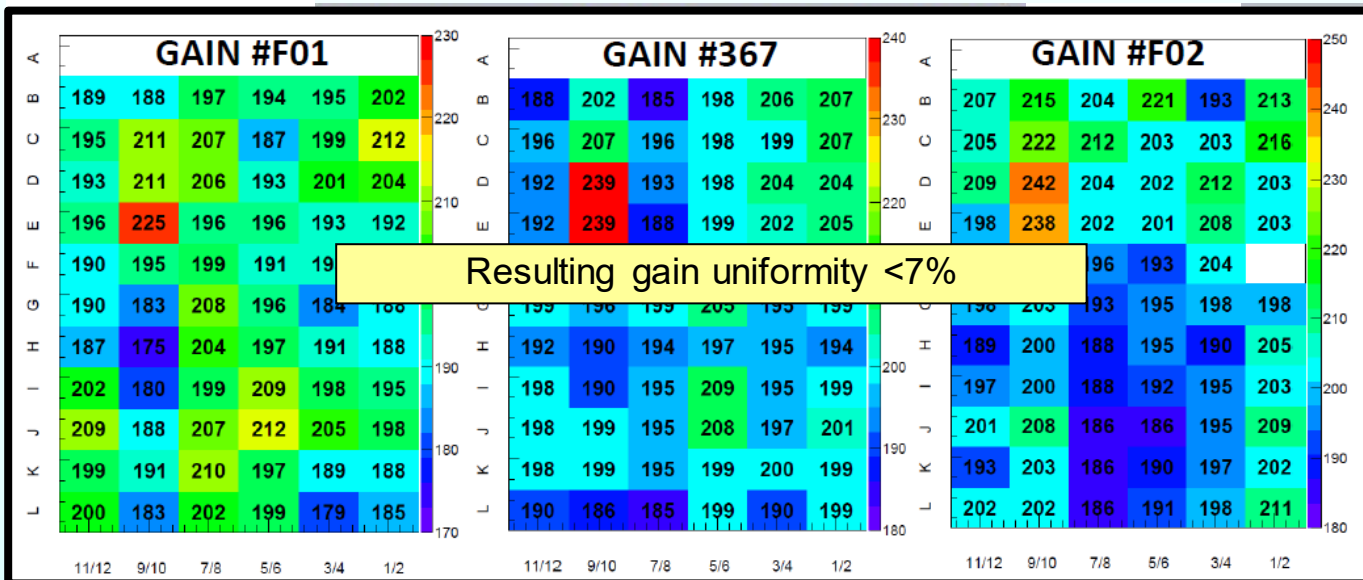


mounting

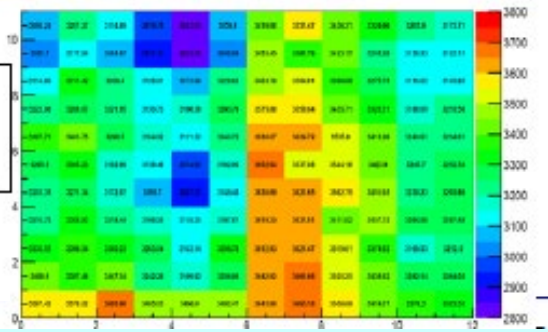
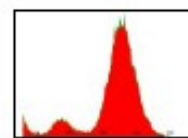


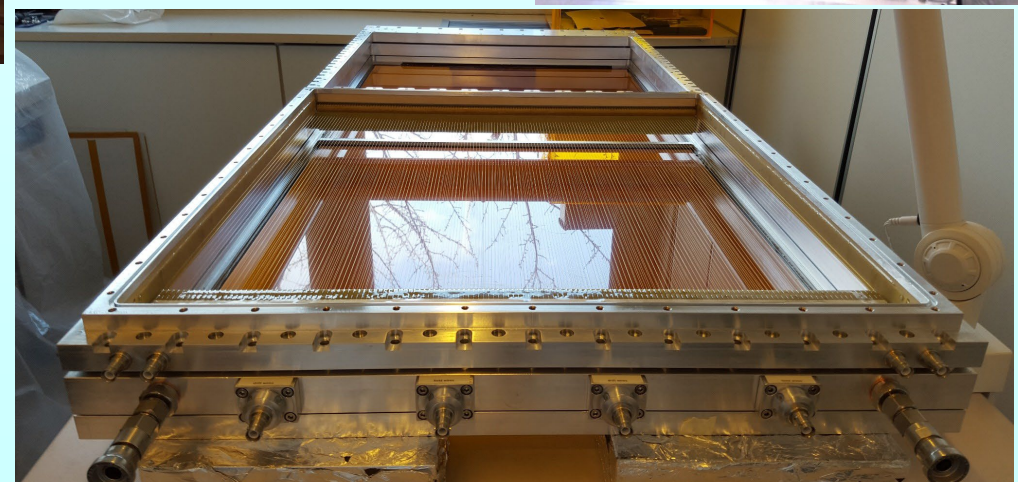
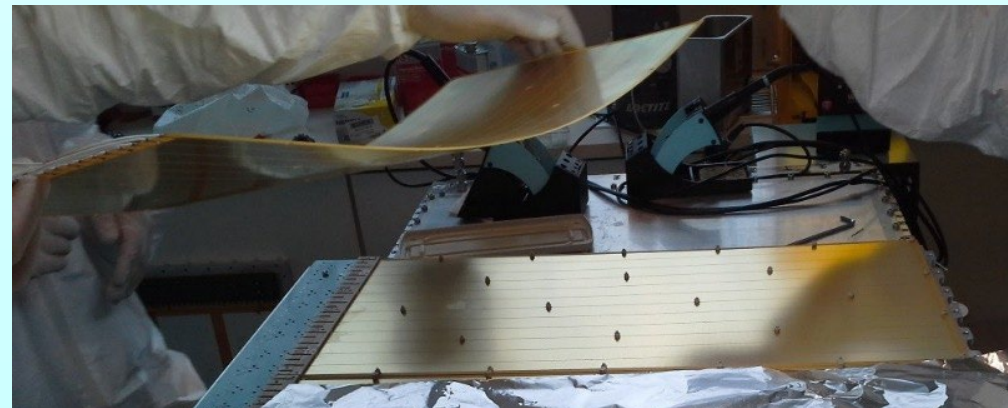
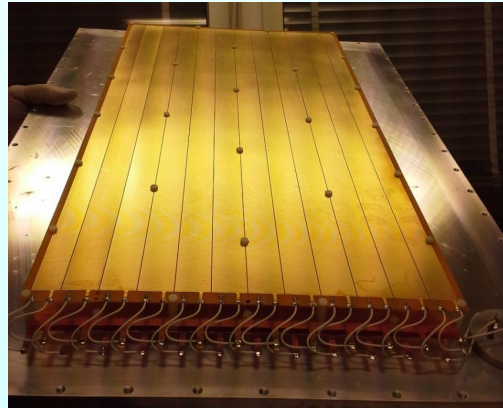
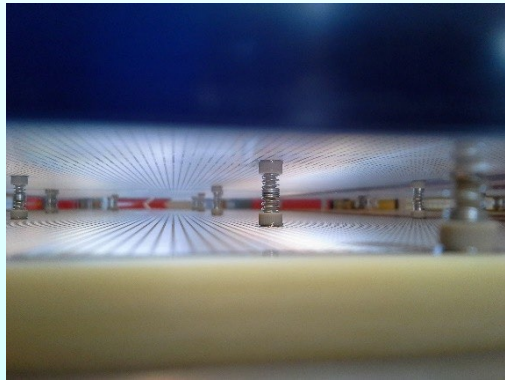
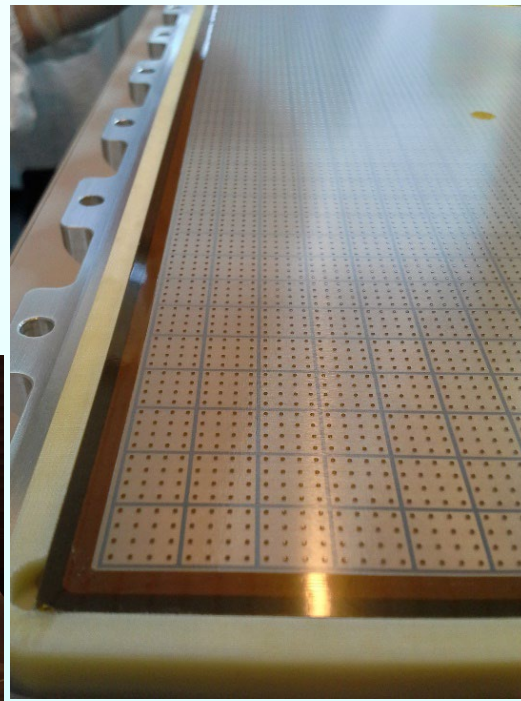
In Trieste a specific cleaning procedure is applied : polish with fine grain pumice powder, pressure water cleaning, ultrasonic Bath with Sonica PCB solution (PH11), distilled water rinsing and oven @ 160 °C



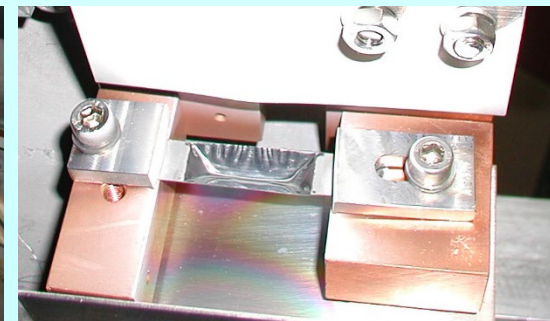
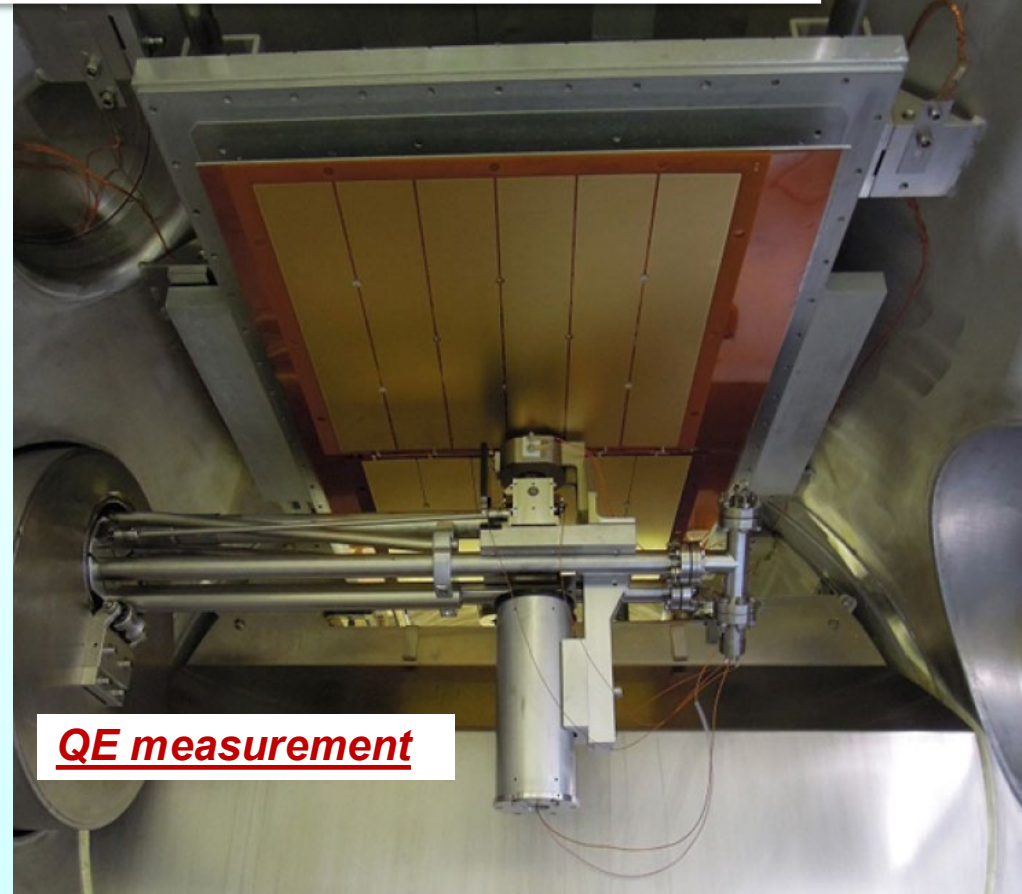
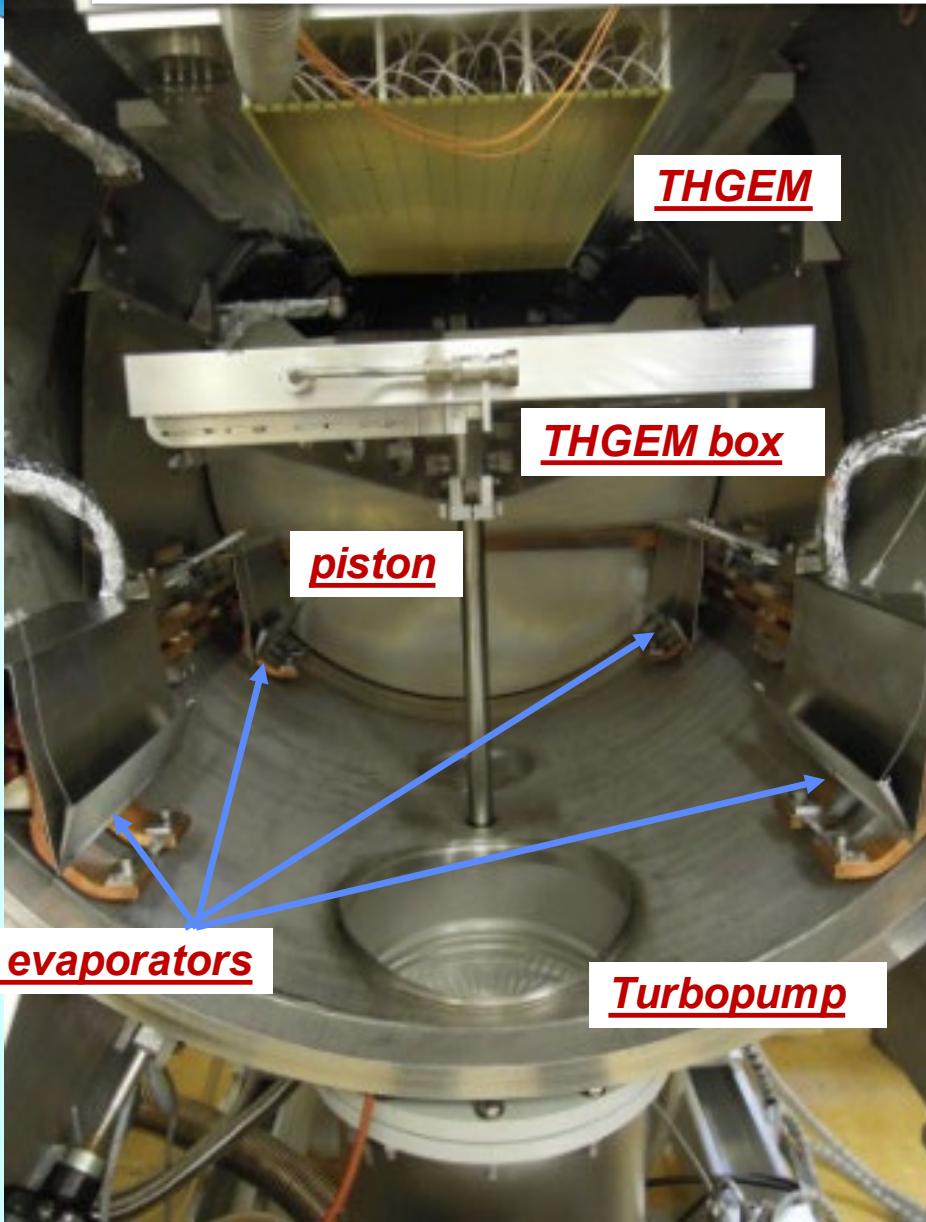


X-ray MM test to access integrity and gain uniformity (<5%)





Csl coating of THGEMs

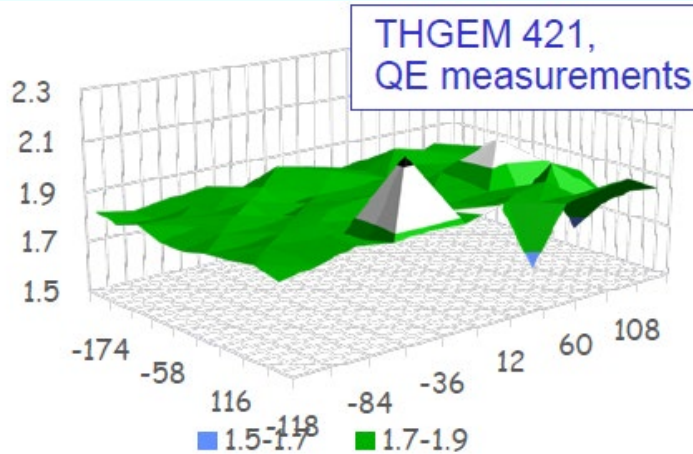




CsI QE measurement

19 CsI evaporations performed at CERN in 2015 - 2016 on 15 pieces: 13 THGEMs, 1 dummy THGEM, and 1 reference piece (best from previous coatings) 11 coated THGEMs available, 8 used + 3 spares

$$I_{Normalized} = \frac{I_{CsI} - I_{CsI_{Noise}}}{I_{Ref} - I_{Ref_{Noise}}}$$



THGEM number	evaporation date	at 60 degrees	at 25 degrees
Thick GEM 319	1/18/2016	2.36	2.44
Thick GEM 307	1/25/2016	2.65	2.47
Thick GEM 407	2/2/2016	2.14	2.47
Thick GEM 418	2/8/2016	2.79	2.98
Thick GEM 410	2/15/2016	2.86	3.14
Thick GEM 429	2/22/2016	2.75	2.74
Thick GEM 334	2/29/2016	2.77	3.00
Thick GEM 421 re-coating	3/10/2016	2.61	2.83
Reference piece	7/4/2016	3.98	3.76

coated by T. Schnider and M. Van Stenis

QE uniformity

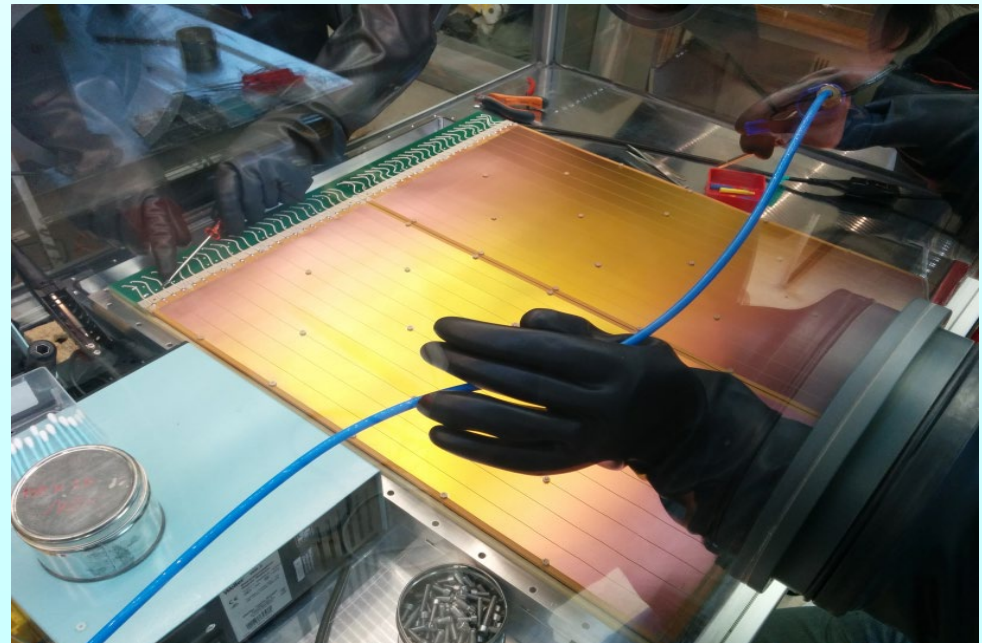
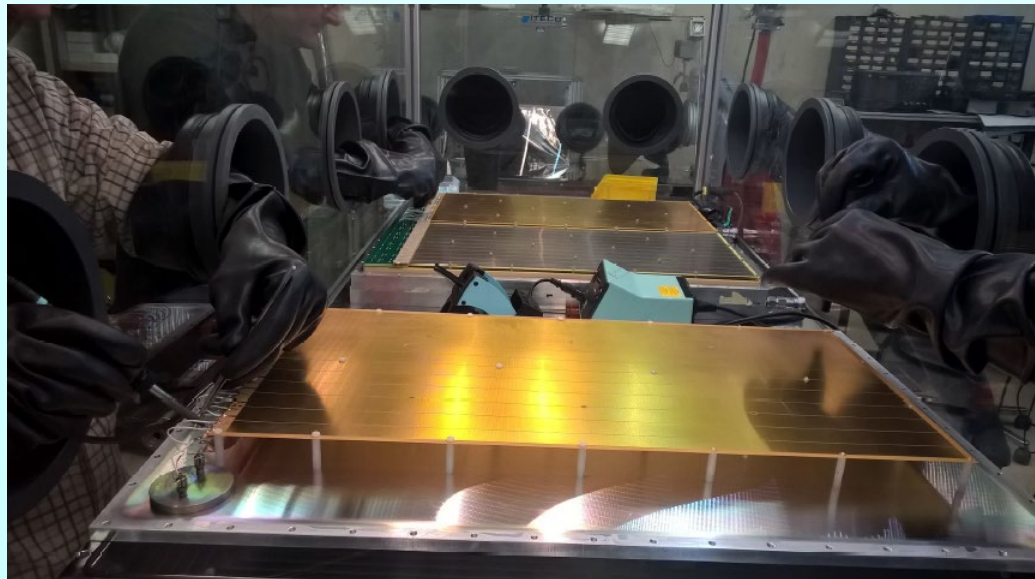
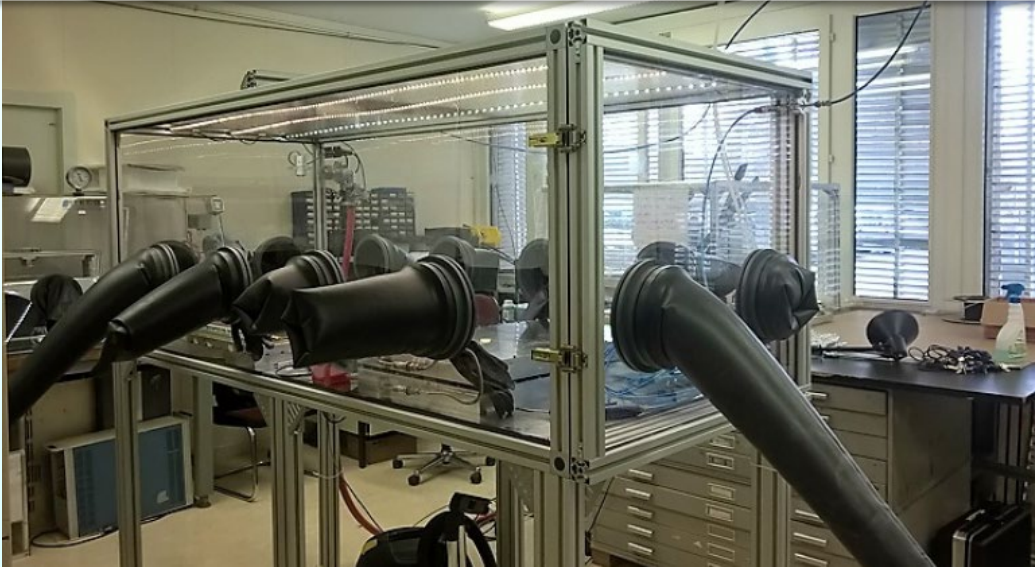
- 3 % r.m.s. within a photocathode
- 10 % r.m.s. among photocathodes

Optical transparency: $\frac{\pi}{2\sqrt{3}} \left(\frac{d}{p}\right)^2 \sim 0.23$



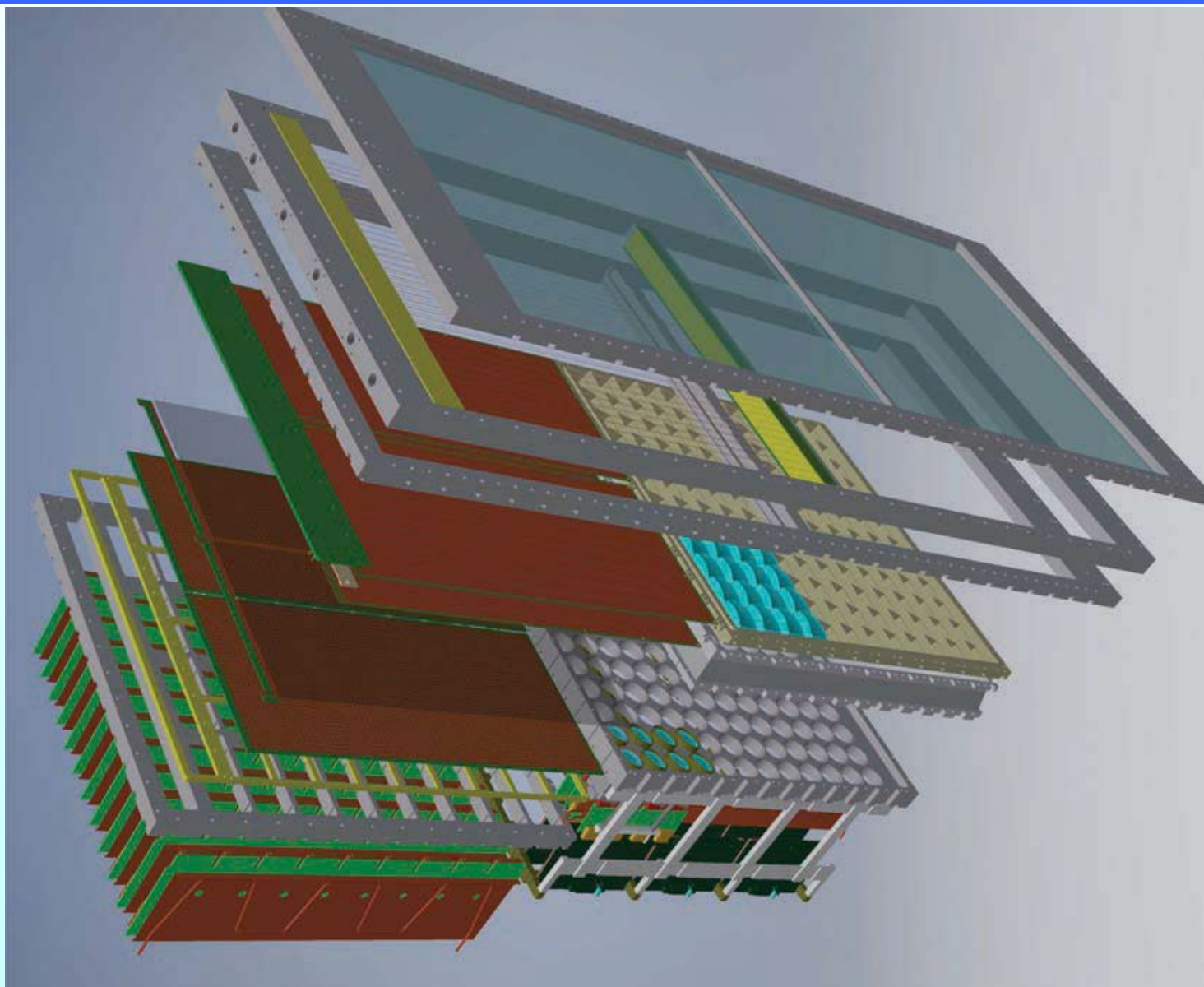
mean THGEM QE: ~ 93% of reference

CsI THGEM mounting





The combined COMPASS PDs



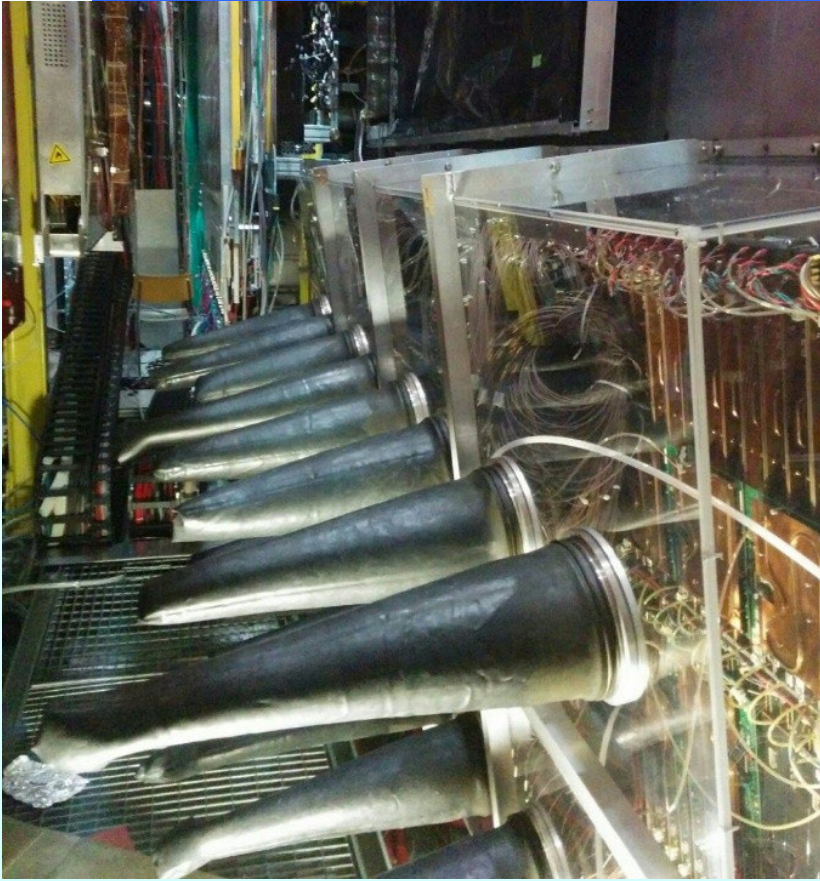


Installation of hybrids on RICH-1





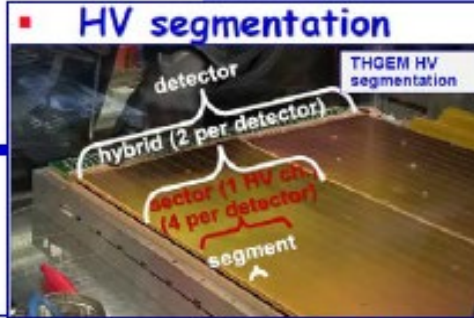
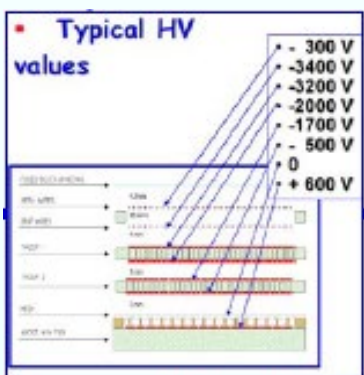
Equipping the hybrids on RICH_1



HV CONTROL

In total 136 HV channels with correlated values

Gain equalization: uniformity at ~1% level



Hardware, commercial by CAEN

HV control

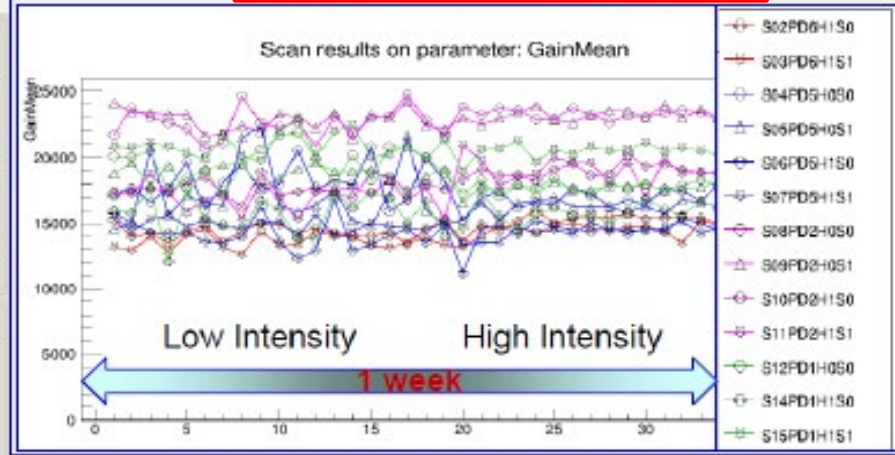
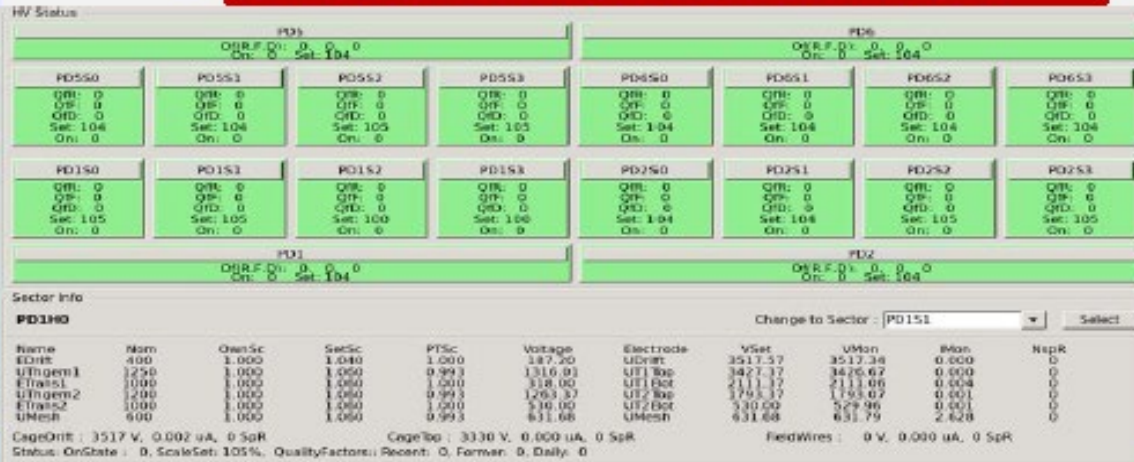
- Custom-made (C++, wxWidgets)
- Compliant with COMPASS DCS (slow control)
- “OwnScale” to fine-tune for gain uniformity
- V, I measured and logged at 1 Hz
- Autodecrease HV if needed (too high spark-rate)
- User interaction via GUI
- Correction wrt P/T to preserve gain stability

Gain stability vs P, T:

- $G = G(V, T/P)$
- Enhanced in a multistage detector
- $\Delta T = 1^\circ\text{C} \rightarrow \Delta G \approx 12\%$
- $\Delta P = 5 \text{ mbar} \rightarrow \Delta G \approx 18\%$

THE WAY OUT:

- Compensate T/P variations by V
- Gain stability at 5% level



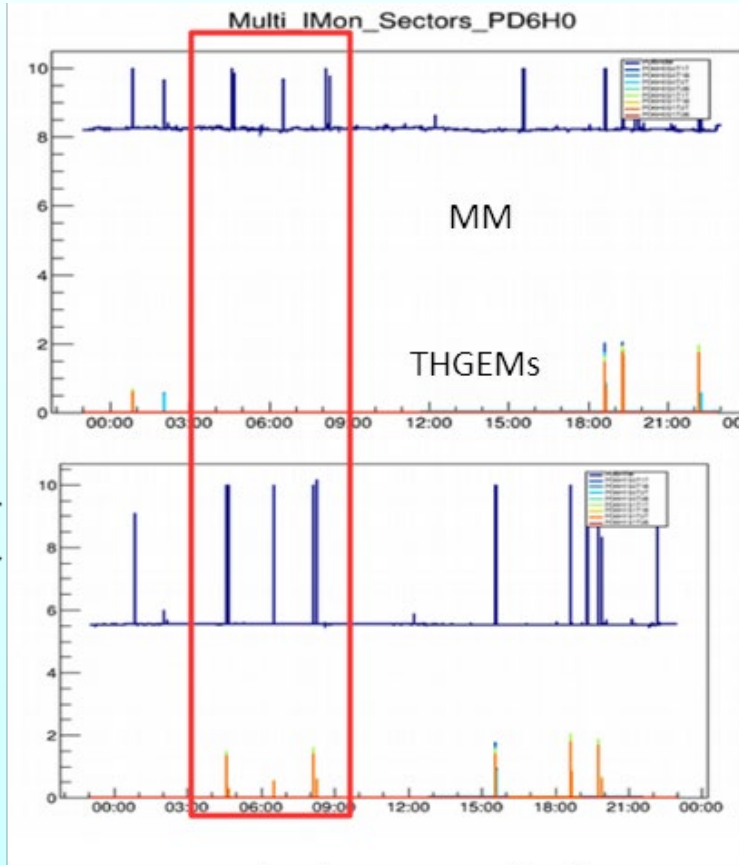
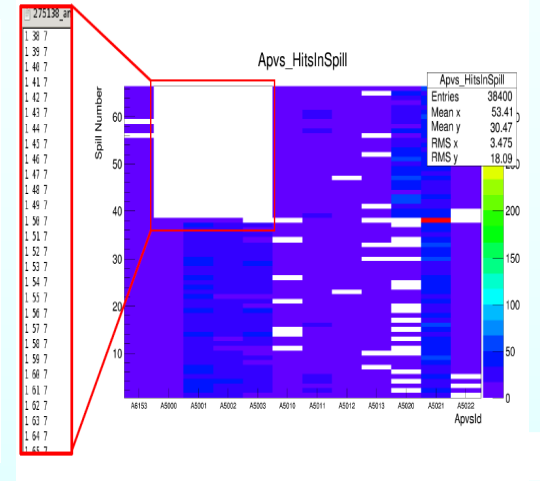
Spark: event with $I > 23$ nA

Current sparks in THGEMs

- Rate $< 1/h$ per detector
- Recovery time: ~ 10 s
- Fully correlated between the two layers
- Mild dependence on beam intensity

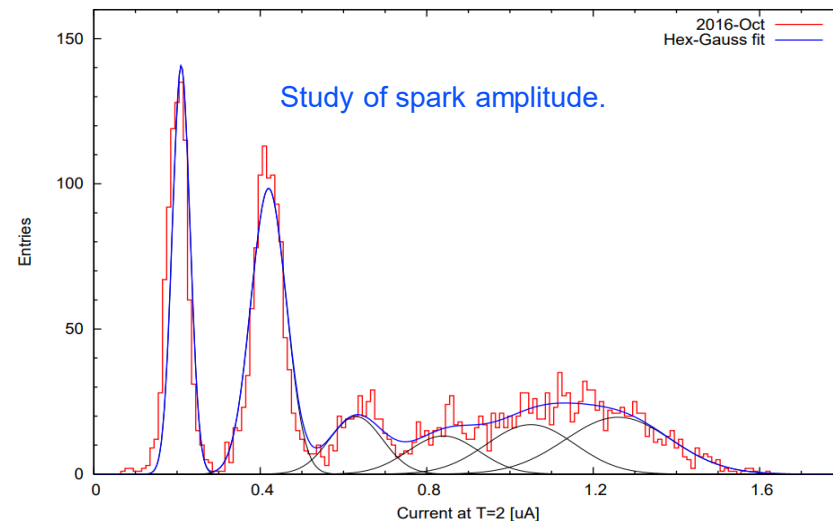
Current sparks in MICROME GAS

- Induced by THGEMs
- Recovery time: ~ 1 s



THGEMs induce sparks in MMs

THGEM Spark Current Values after T=2sec (avg) with Gaussian fits



Some sparks produce APV errors.

APV header error related to data scrambling.

Missing hits and data attributed to different channels.

➔ Automatic APV reload procedure as soon as APV header errors are detected.



Gain stability in time

cath2

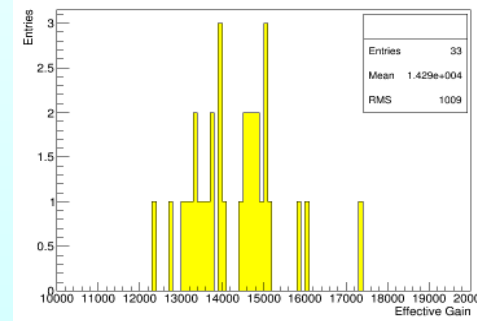
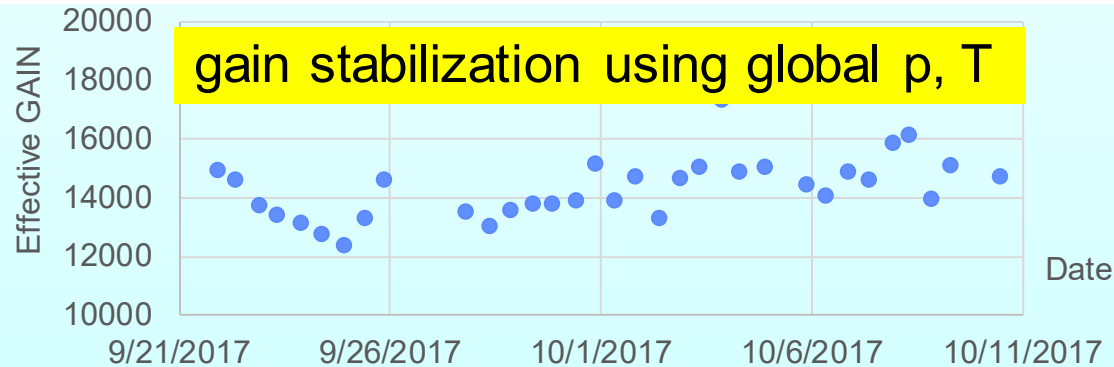
cath2	
Entries	155658
Mean	47.68 ± 0.1207
RMS	47.64 ± 0.08537
Underflow	0
Overflow	0
Integral(w)	1.557e+05
χ ² / ndf	294.1 / 147
Prob	7.051e-12
p0	3081 ± 41.0
p1	0.02127 ± 0.00014

14104.8 ± 91.7

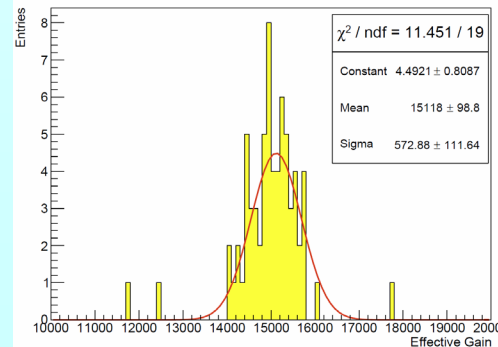
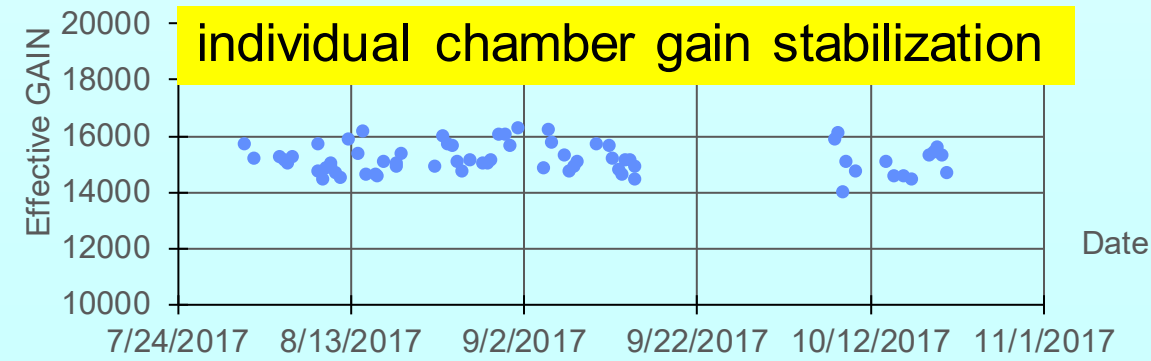
cath4

cath4	
Entries	108330
Mean	42.63 ± 0.142
RMS	46.73 ± 0.1004
Underflow	0
Overflow	0
Integral(w)	1.083e+05
χ ² / ndf	244.8 / 147
Prob	7.381e-07
p0	1845 ± 31.9
p1	0.02147 ± 0.00018

13976.1 ± 117.1



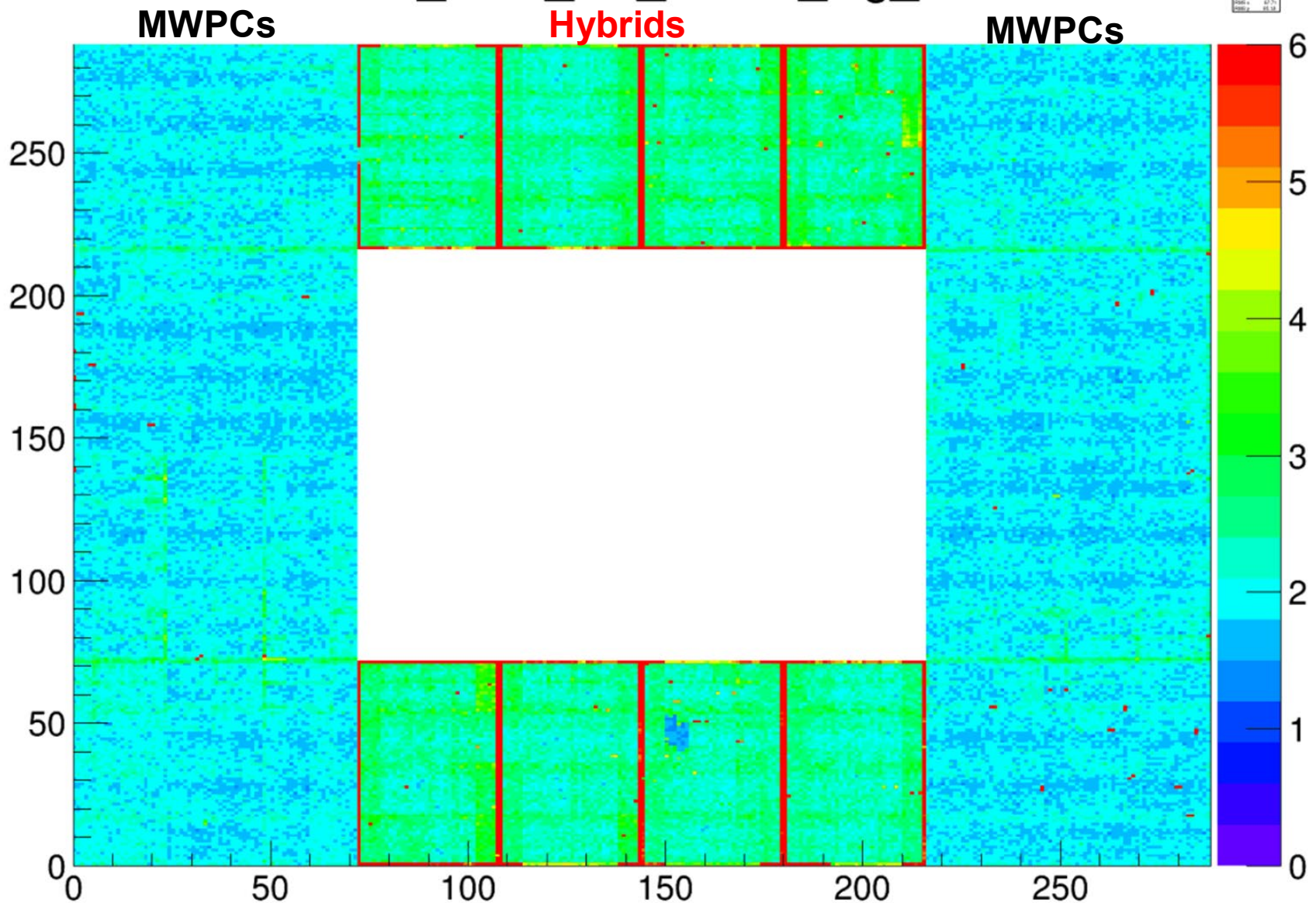
global corrections:
σ/mean ~ 7%



individual corrections:
σ/mean ~ 4%

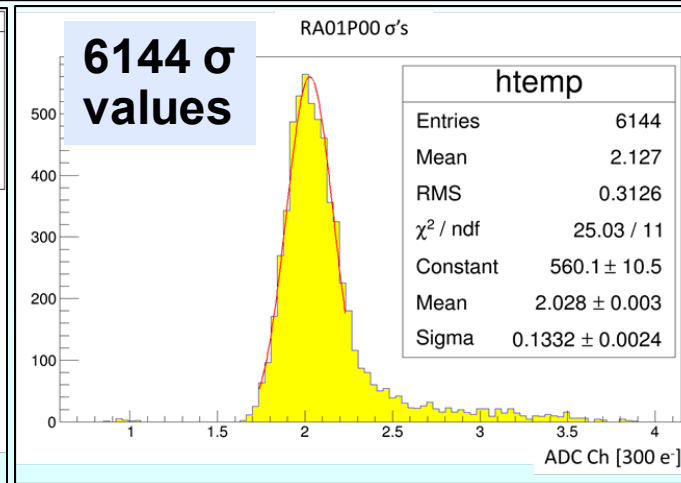
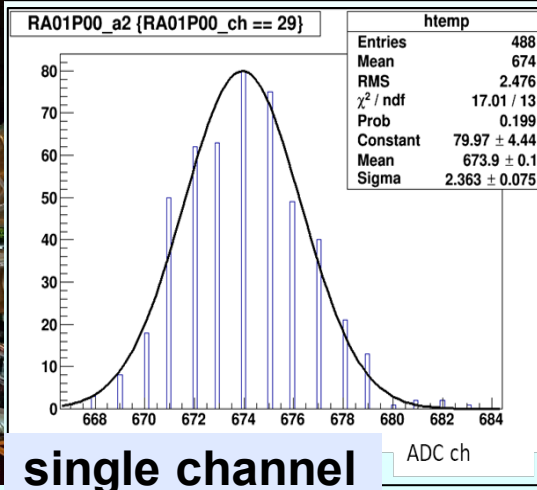
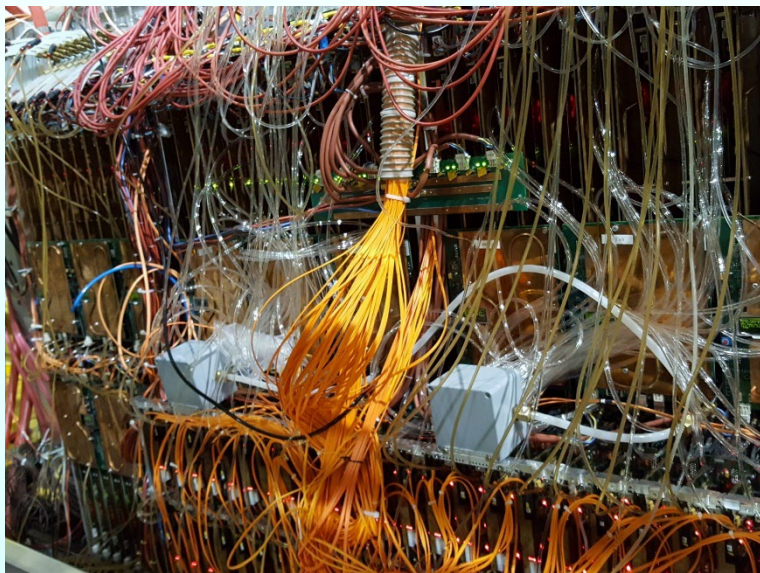


Noise figure for the 62208 ch.

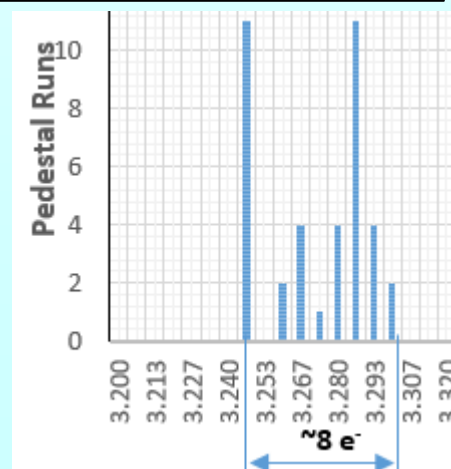
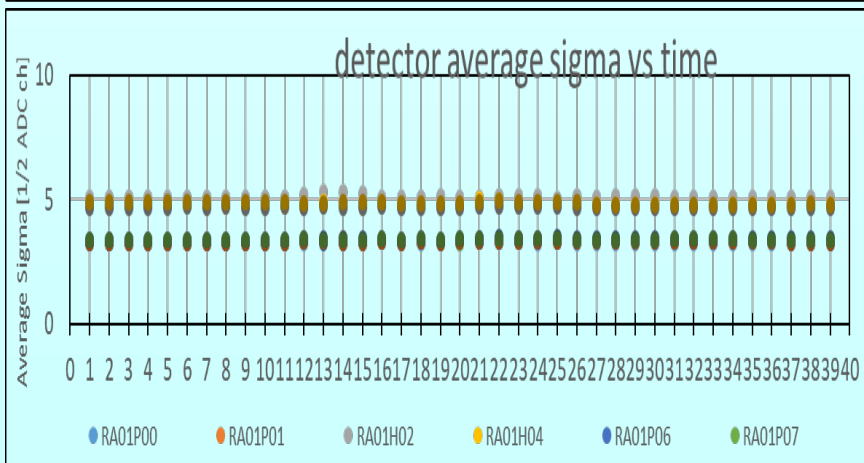


Noise level and pedestal stability

- 12 Detectors, 6144 Ch each.



- 39 APV Pedestal Runs during COMPASS 2017 run.



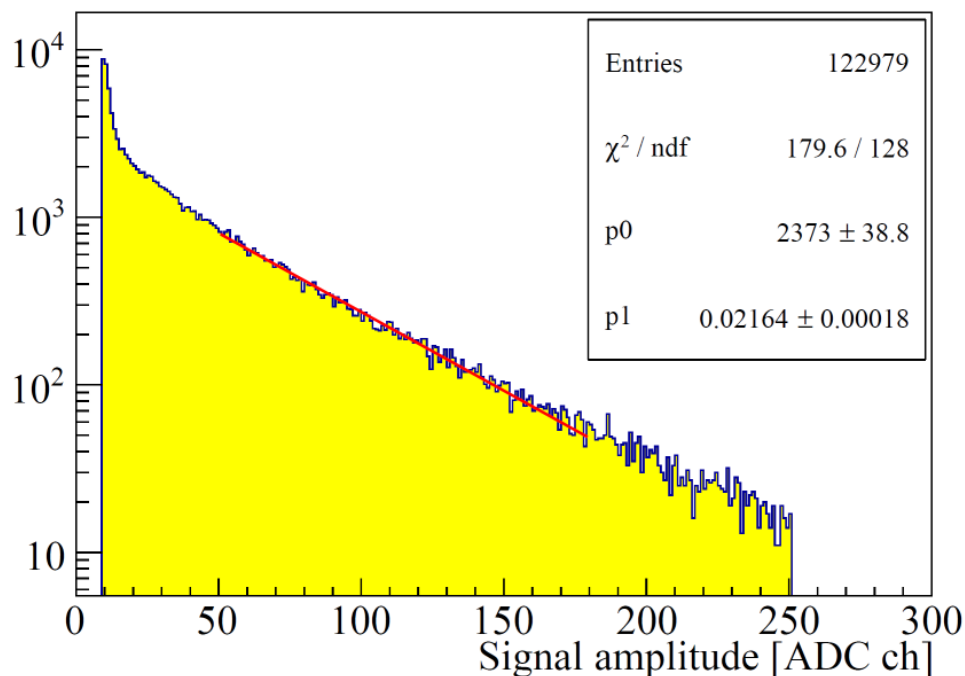
The APV25-based F/E is the same for MWPCs +CsI and Hybrid PD's

The noise levels are:

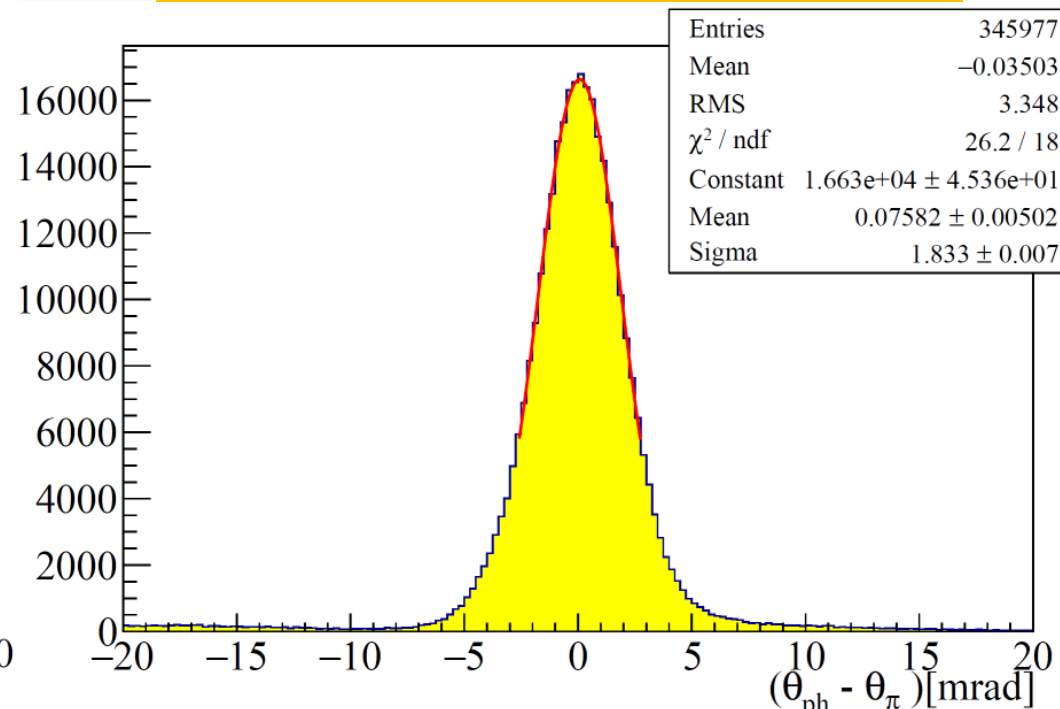
- MWPC: $\sim 600 e^-$
- **Hybrid: $\sim 800 e^-$**

The noise levels are very stable in time

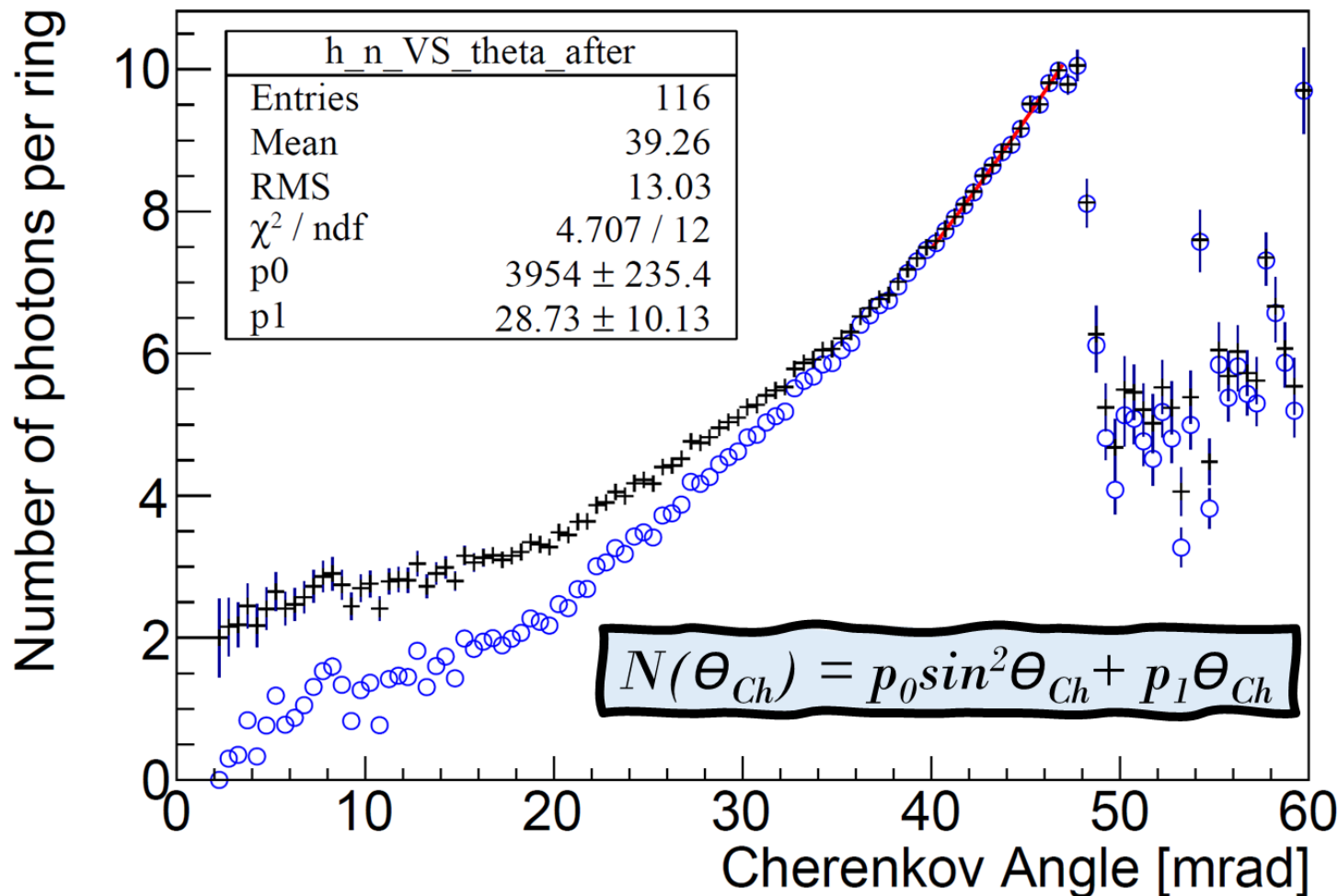
Effective gain : $\sim 14000 \pm 140$



Single photon resolution: 1.83 ± 0.01 mrad



The COMPASS/AMBER MPGD-based PDs have been stably operating since years.



Extrapolate to saturation, number of photon= **12.9**
 First part of the function = 11.5 ± 0.4
 Second part of the function = 1.4 ± 0.3

The COMPASS/AMBER MPGD-based PDs have 11.5 average detected photons per ring at saturation, higher gain and higher stability than the MWPCs +CsI.

STCF

Conceptual Design Report

Abstract

The Super τ -Charm facility (STCF) is an electron-positron collider proposed by the Chinese particle physics community. It is designed to operate in a center-of-mass energy range from 2 to 7 GeV with a peak luminosity of $0.5 \times 10^{35} \text{ cm}^{-2}\text{s}^{-1}$ or higher. The STCF will produce a data sample about a factor of 100 larger than that of the present τ -Charm factory — the BEPCII, providing a unique platform for exploring the asymmetry of matter-antimatter (charge-parity violation), in-depth studies of the internal structure of hadrons and the nature of non-perturbative strong interactions, as well as searching for exotic hadrons and physics beyond the Standard Model. The STCF project in China is under development with an extensive R&D program. This document presents the physics opportunities at the STCF, describes conceptual designs of the STCF detector system, and discusses future plans for detector R&D and physics case studies.

arXiv:2303.15790v3 [hep-ex] 5 Oct 2023

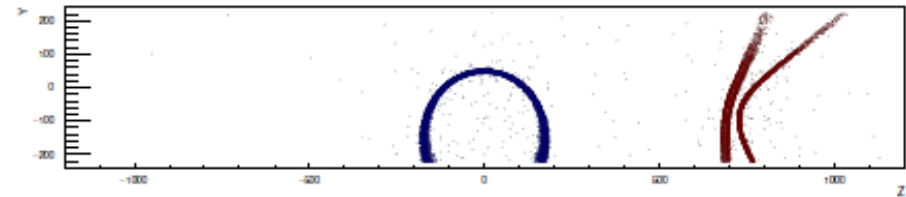
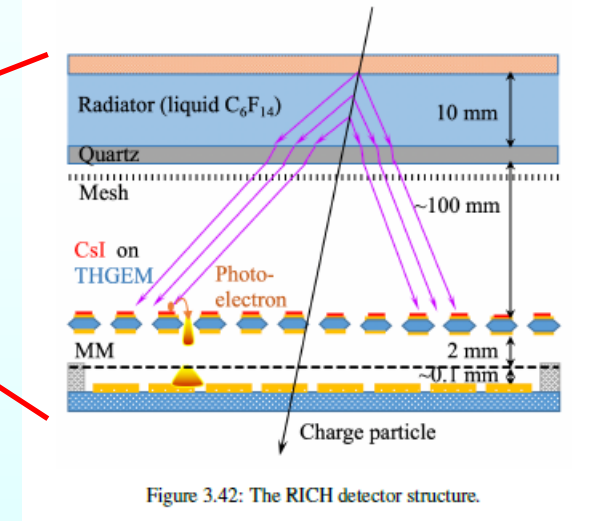
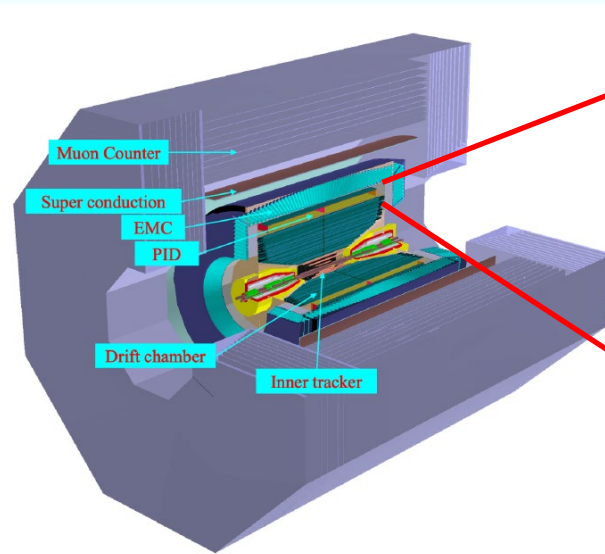


Figure 3.46: Examples of Cherenkov images in a RICH module. The blue image depicts the distribution of hits for 2 GeV/c pion with incident angle $\theta = 0^\circ$, perpendicular to RICH, while the red image depicts $\theta = 40^\circ$.

Hybrid THGEM-Micromegas PD's have recently been proposed for the RICH of the STCF



CONCLUSIONS

- **COMPASS RICH-1 has been upgraded with 1.4 m² of MPGD-based PDs.**
- **Specific solutions to achieve control over THGEM gain response.**
- **The Hybrid PD: 2 THGEMs (1 with CsI) + Micromegas are nicely operating.**
- **Good stability, low IBF, low spark rate. Spark effects mitigation measures.**
- **1.83 mrad single photon angular resolution, 11.5 detected photons per ring.**
- **Future RICH projects are considering the use of this technology.**